



US010439161B2

(12) **United States Patent**
Park et al.

(10) **Patent No.:** **US 10,439,161 B2**
(45) **Date of Patent:** **Oct. 8, 2019**

(54) **METHOD OF MANUFACTURING A DISPLAY PANEL CAPABLE OF PREVENTING A DEFECT IN LIGHT EMISSION OF AN ORGANIC LIGHT EMITTING ELEMENT**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **16/020,572**

(22) Filed: **Jun. 27, 2018**

(65) **Prior Publication Data**

US 2018/0309085 A1 Oct. 25, 2018

Related U.S. Application Data

(62) Division of application No. 15/646,362, filed on Jul. 11, 2017, now Pat. No. 10,020,461.

(30) **Foreign Application Priority Data**

Jul. 18, 2016 (KR) 10-2016-0090947

(51) **Int. Cl.**
H01L 51/50 (2006.01)
H01L 51/52 (2006.01)
(Continued)

(52) **U.S. Cl.**
CPC **H01L 51/5228** (2013.01); **H01L 27/3209** (2013.01); **H01L 27/3246** (2013.01);
(Continued)

(58) **Field of Classification Search**
CPC . H01L 51/50; H01L 51/5206; H01L 51/5212; H01L 51/5228; H01L 51/56
See application file for complete search history.

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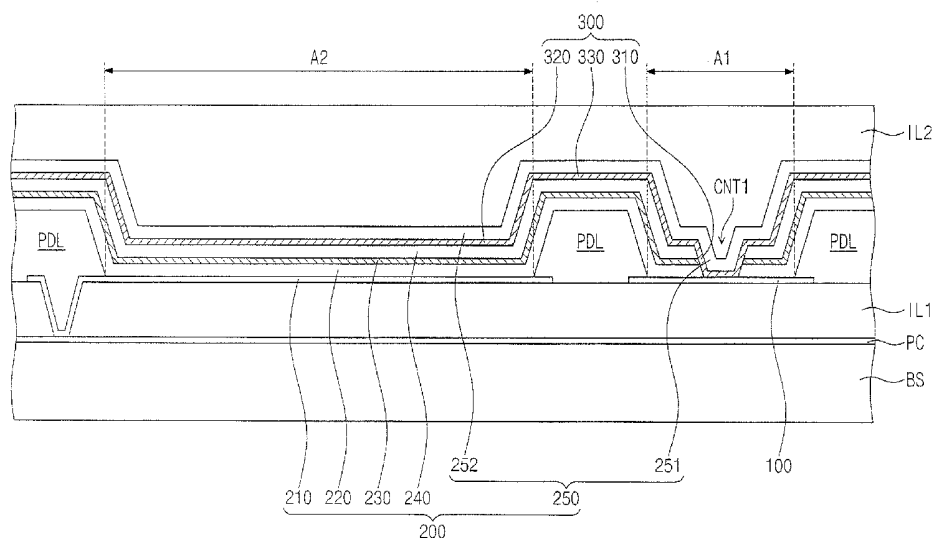
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(57) **ABSTRACT**

A display panel includes an auxiliary electrode on a base substrate, a first electrode spaced from the auxiliary electrode, a first light emitting unit on the auxiliary electrode and the first electrode, an conductive thin film layer on the first light emitting unit, a second light emitting unit on the conductive thin film layer, a first contact hole through the conductive thin film layer to expose the auxiliary electrode, a insulating layer in the first contact hole, and a second electrode including a first electrode part and a second electrode part, the first electrode part being on the insulating layer in the first contact hole, and the second electrode part overlapping the first electrode and being on the second light emitting unit, wherein the insulating layer is between the first electrode part and the conductive thin film layer.

4 Claims, 17 Drawing Sheets



- (51) **Int. Cl.**
H01L 51/00 (2006.01)
H01L 27/32 (2006.01)
H01L 51/56 (2006.01)
- (52) **U.S. Cl.**
CPC *H01L 51/0096* (2013.01); *H01L 51/5044*
(2013.01); *H01L 51/5206* (2013.01); *H01L*
51/56 (2013.01); *H01L 2251/301* (2013.01);
H01L 2251/5392 (2013.01); *H01L 2251/558*
(2013.01)

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FIG. 1

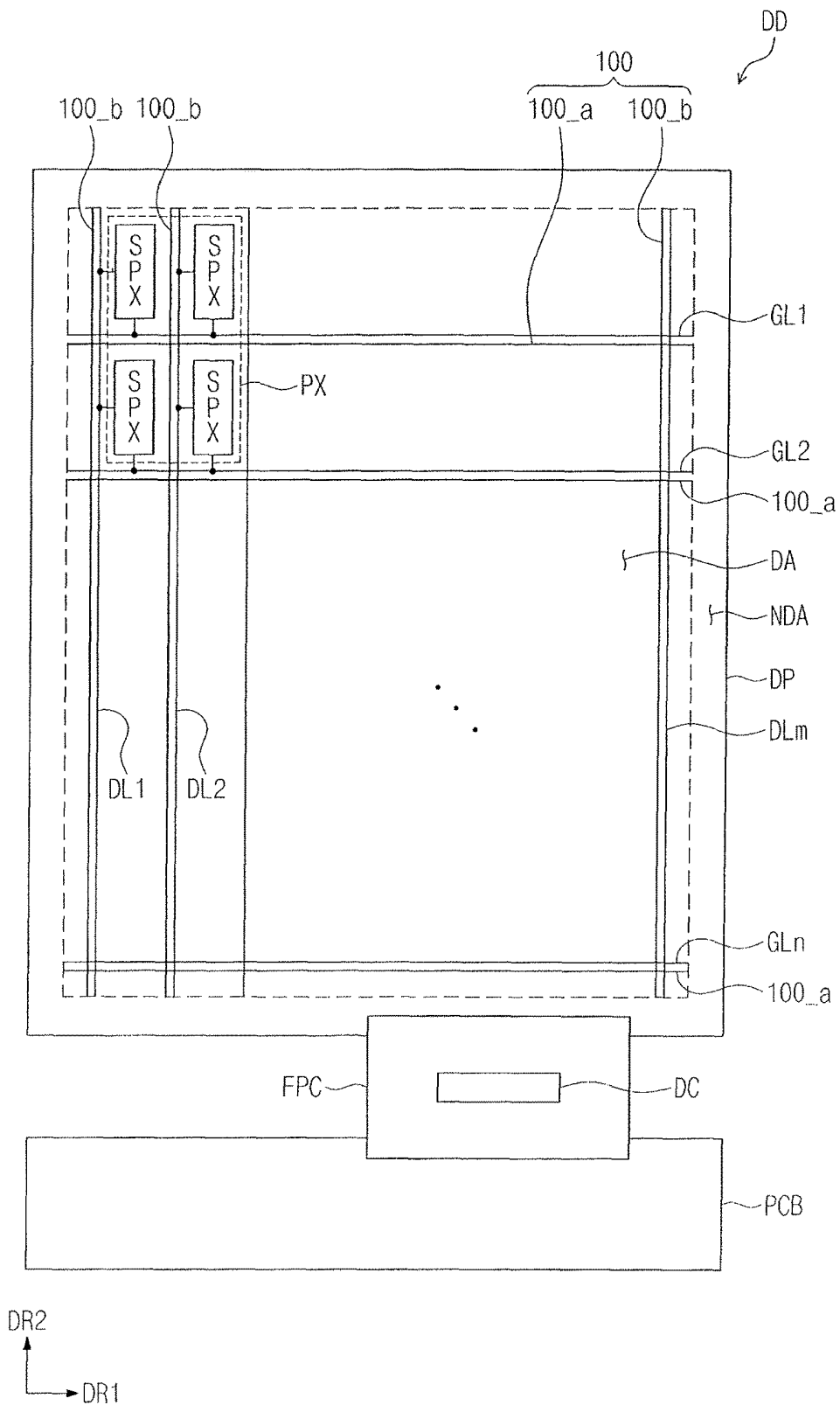


FIG. 2

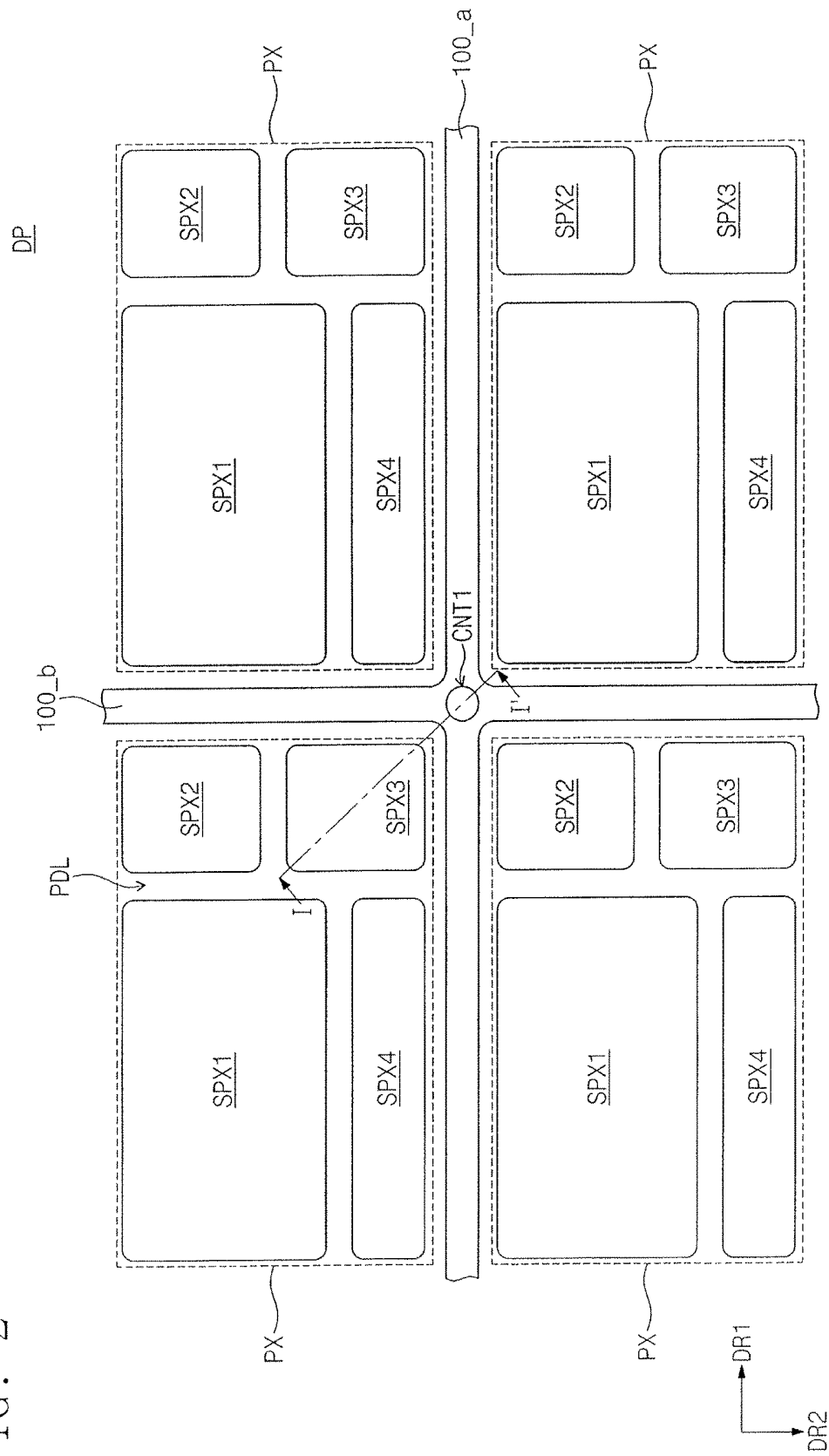


FIG. 3A

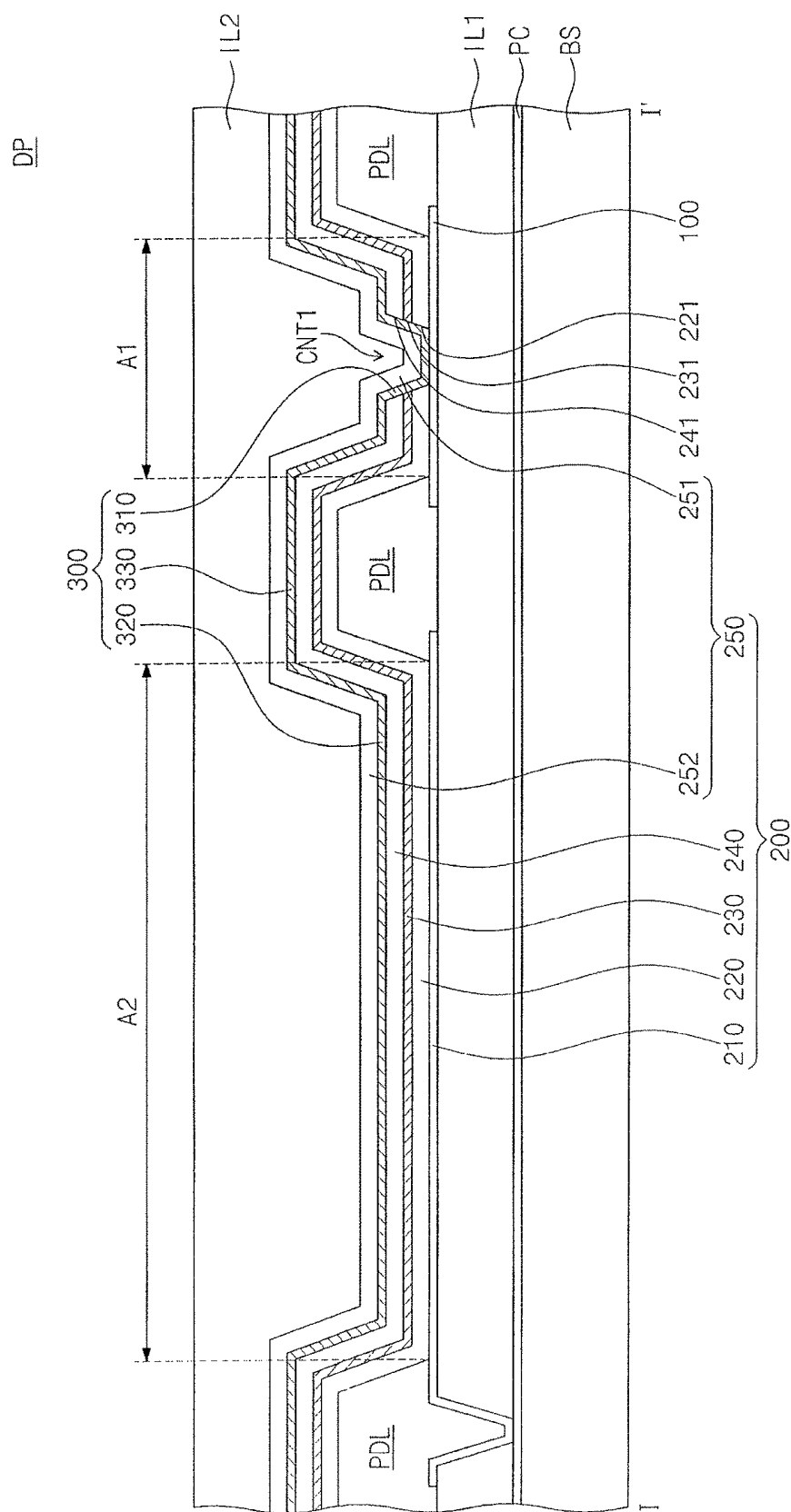


FIG. 3B

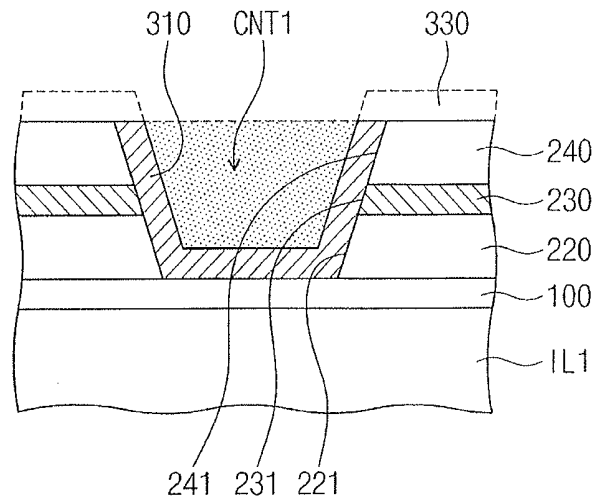


FIG. 3C

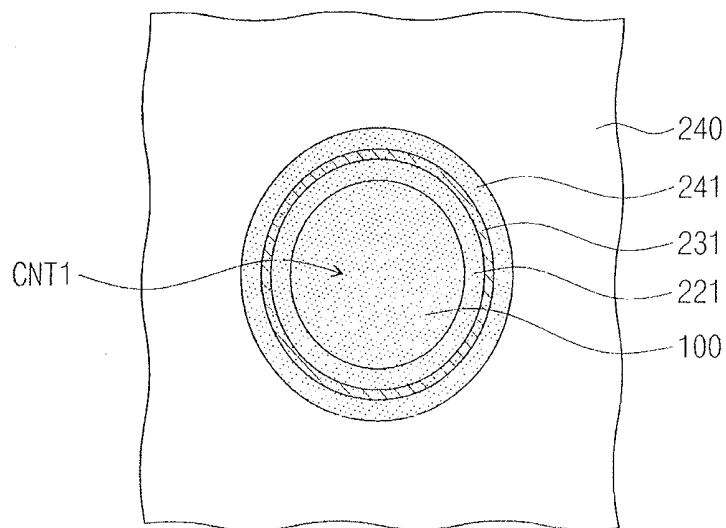


FIG. 3D

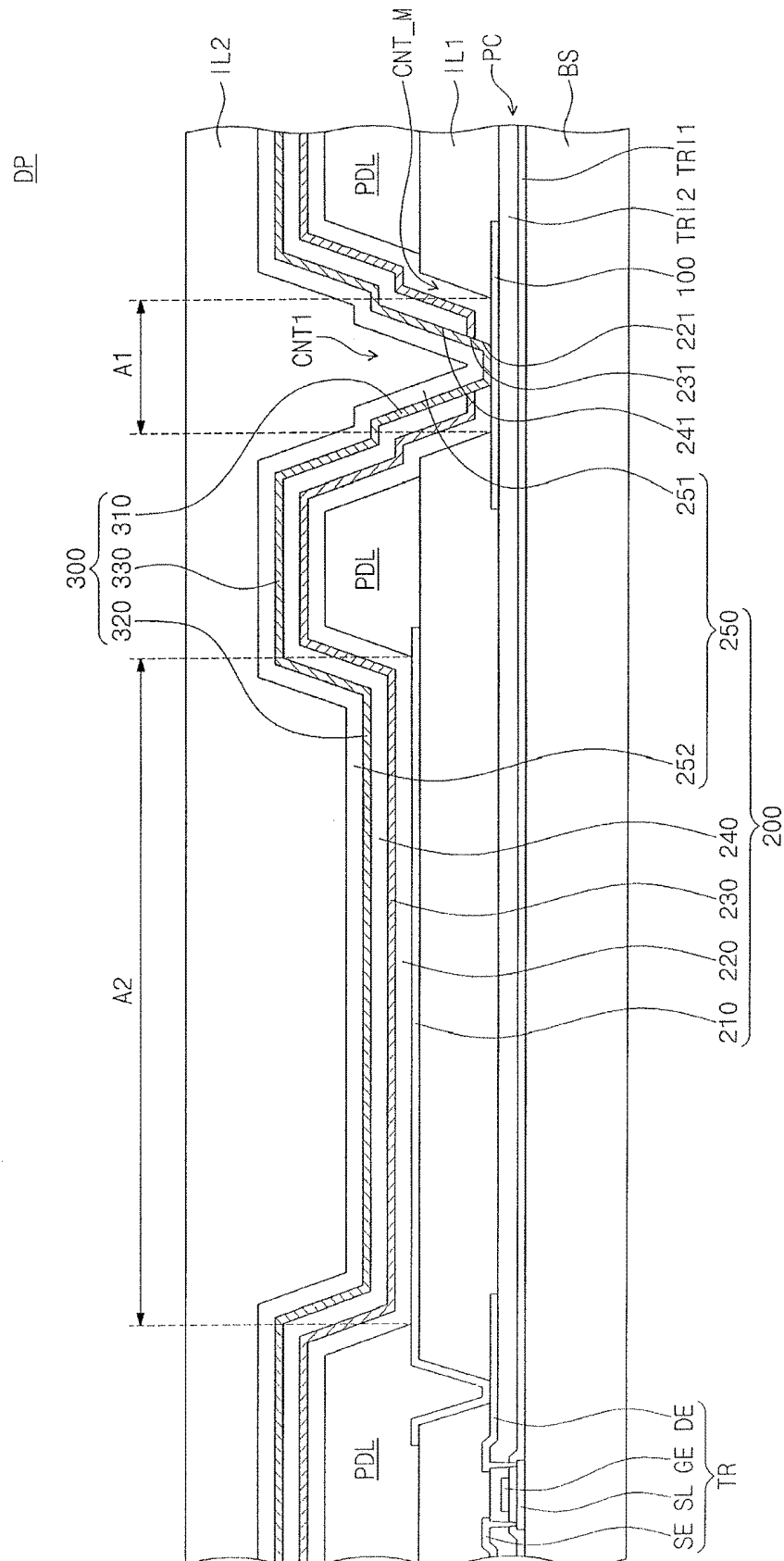


FIG. 4.

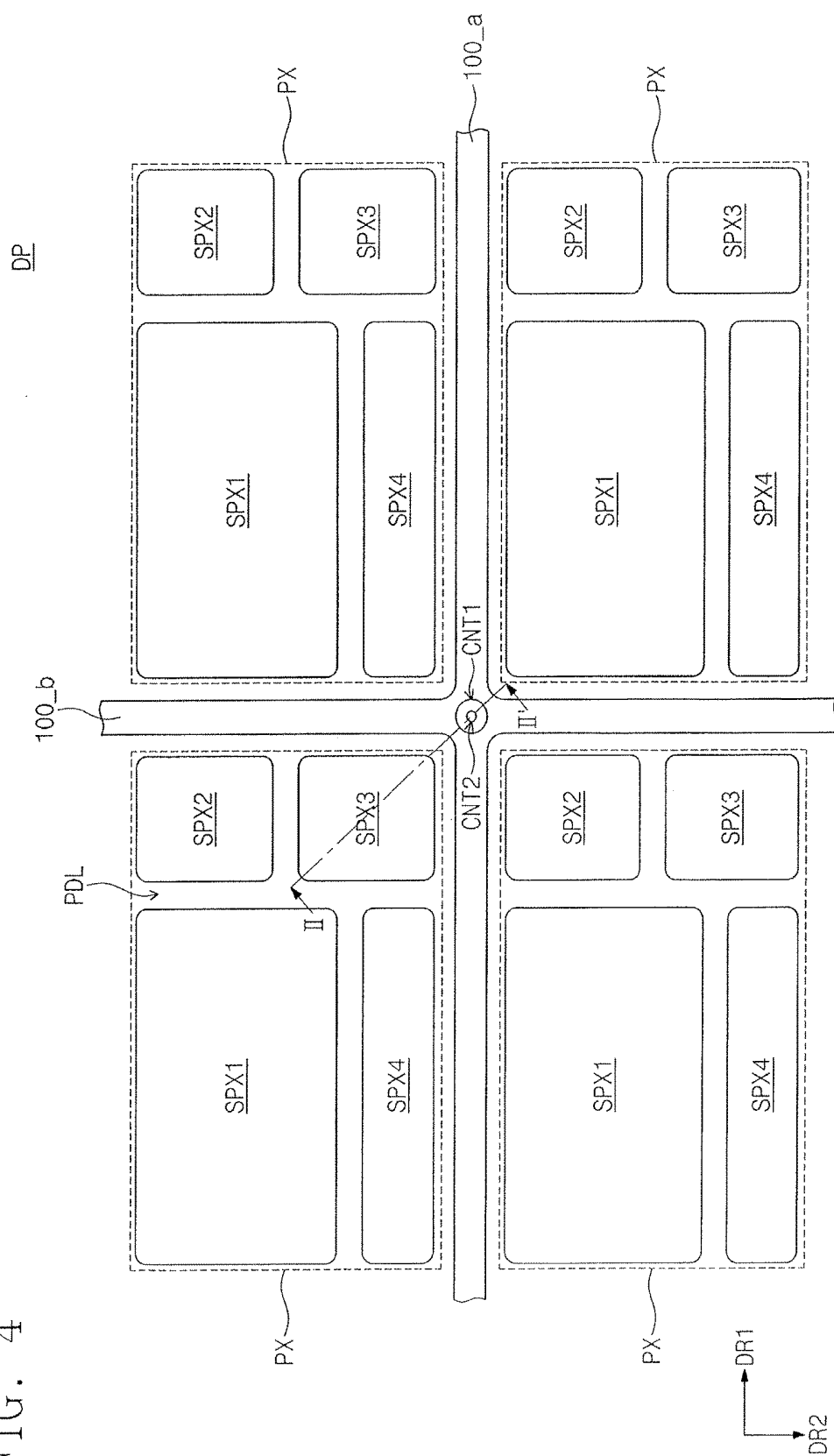


FIG. 5

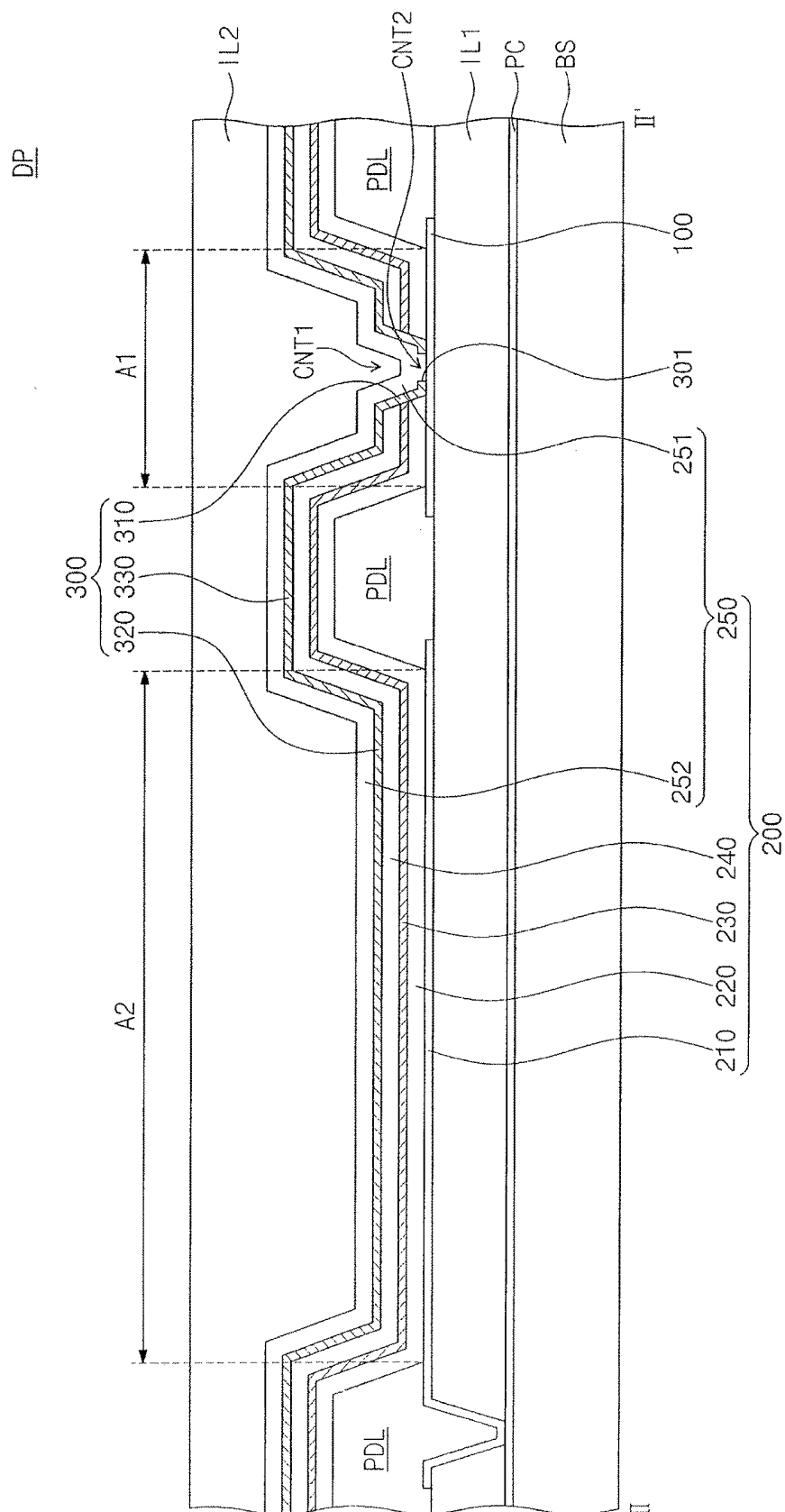


FIG. 6

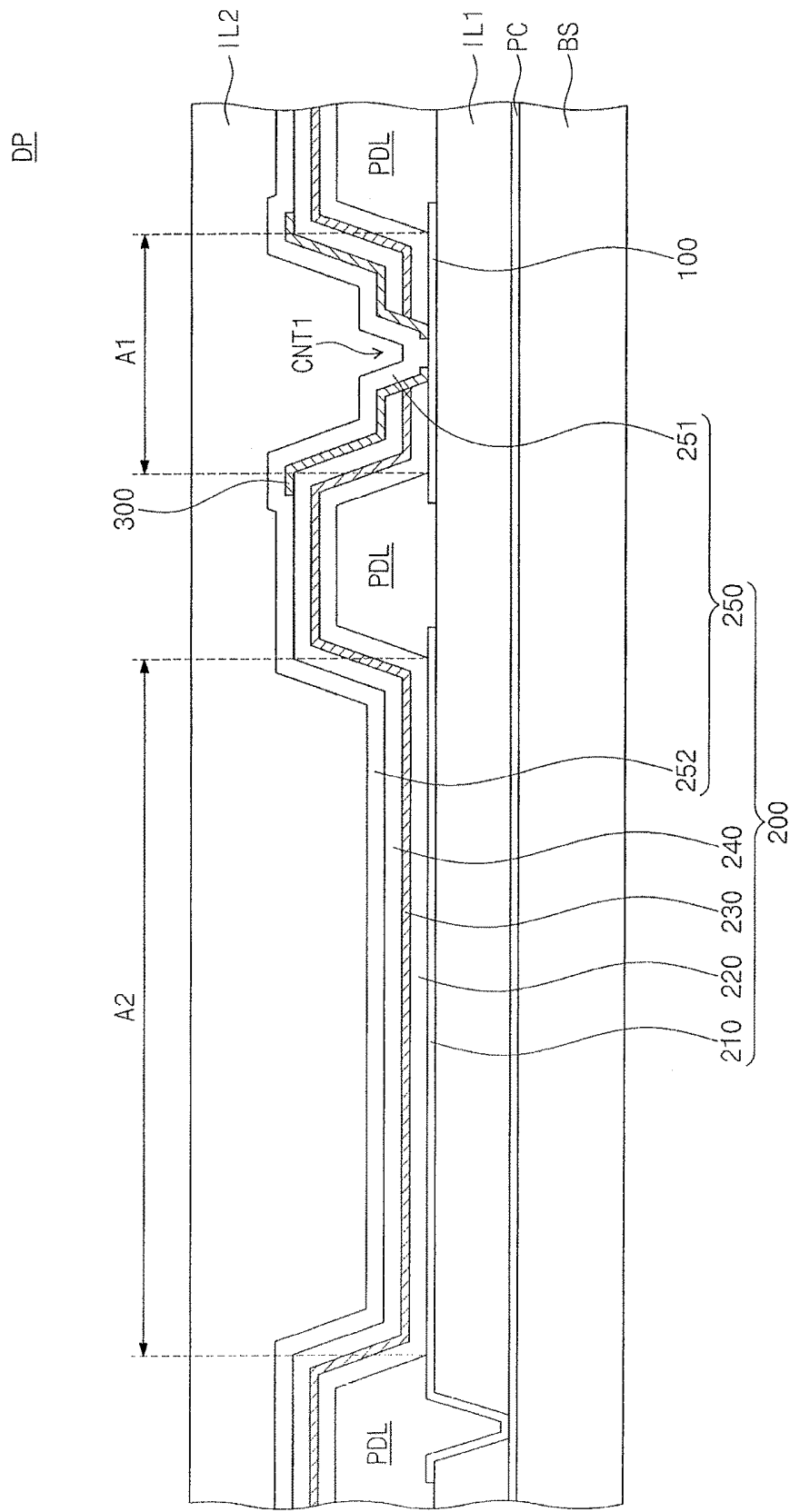


FIG. 7

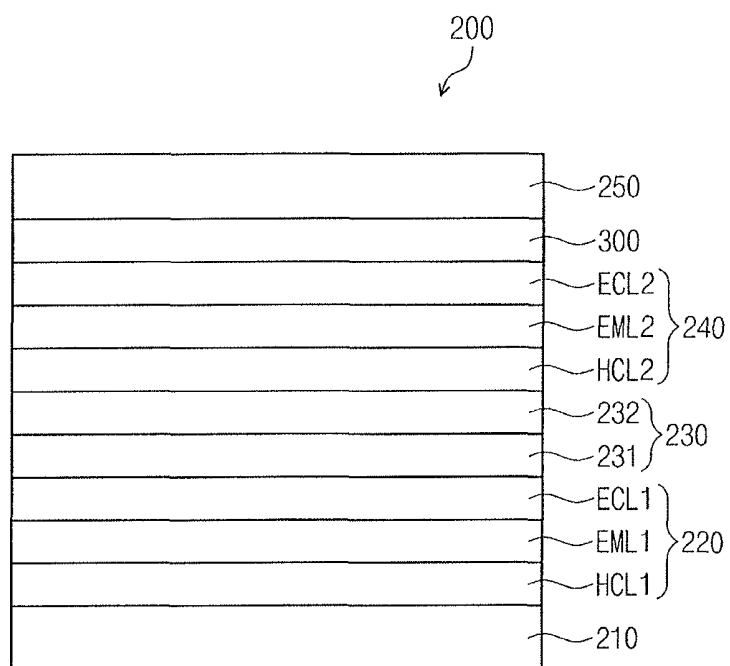


FIG. 8A

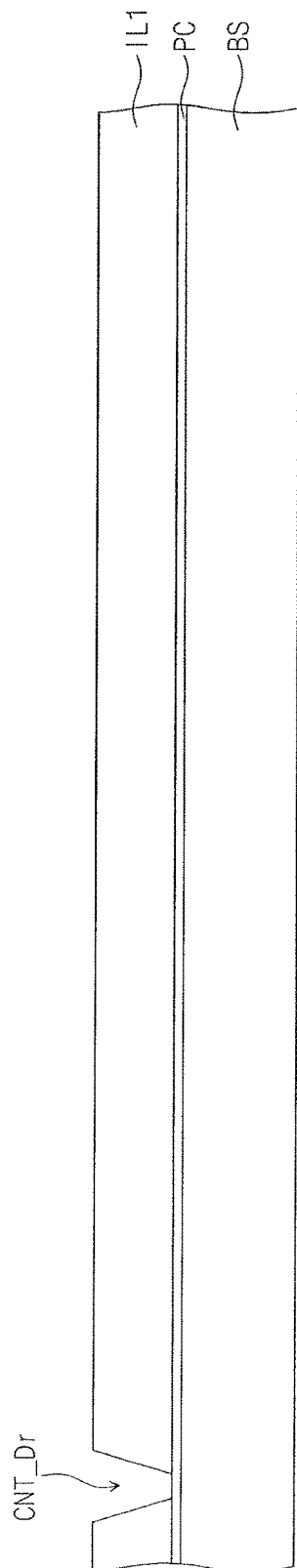


FIG. 8B

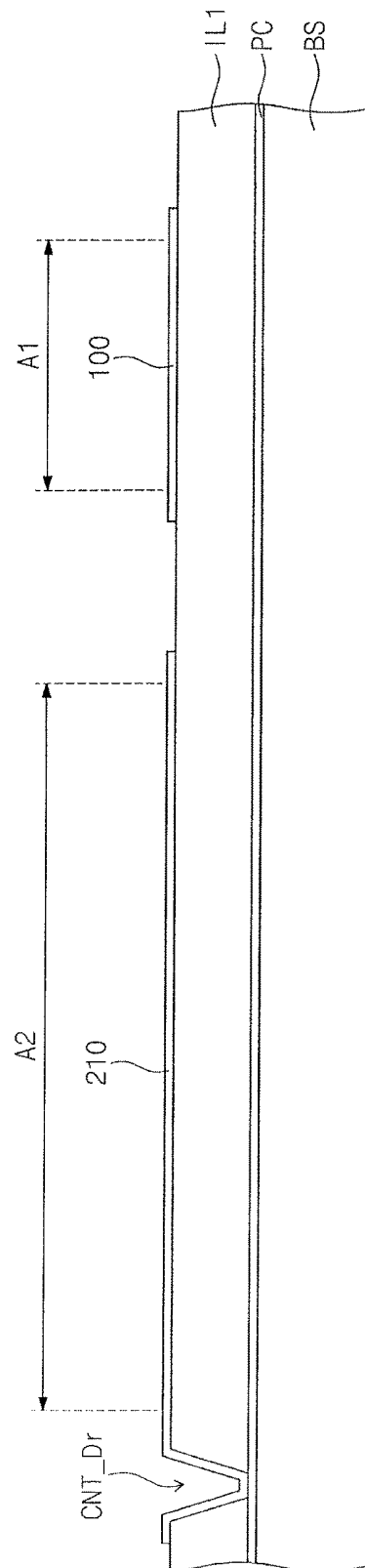


FIG. 8C

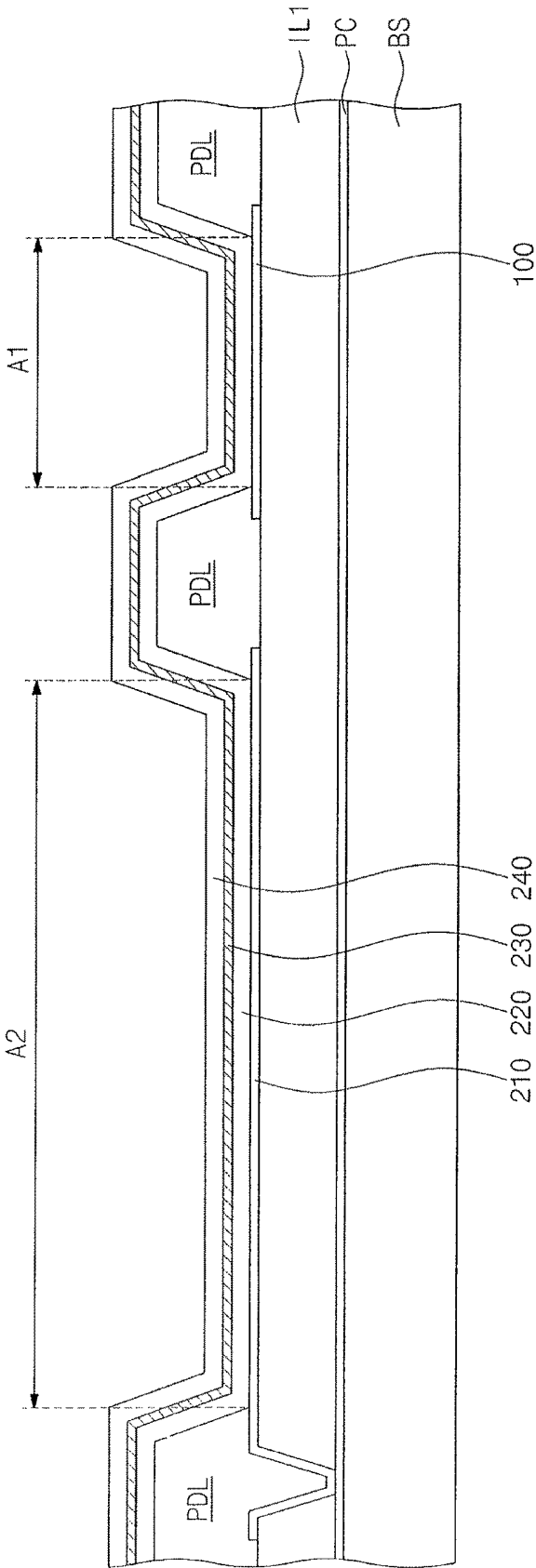


FIG. 8F

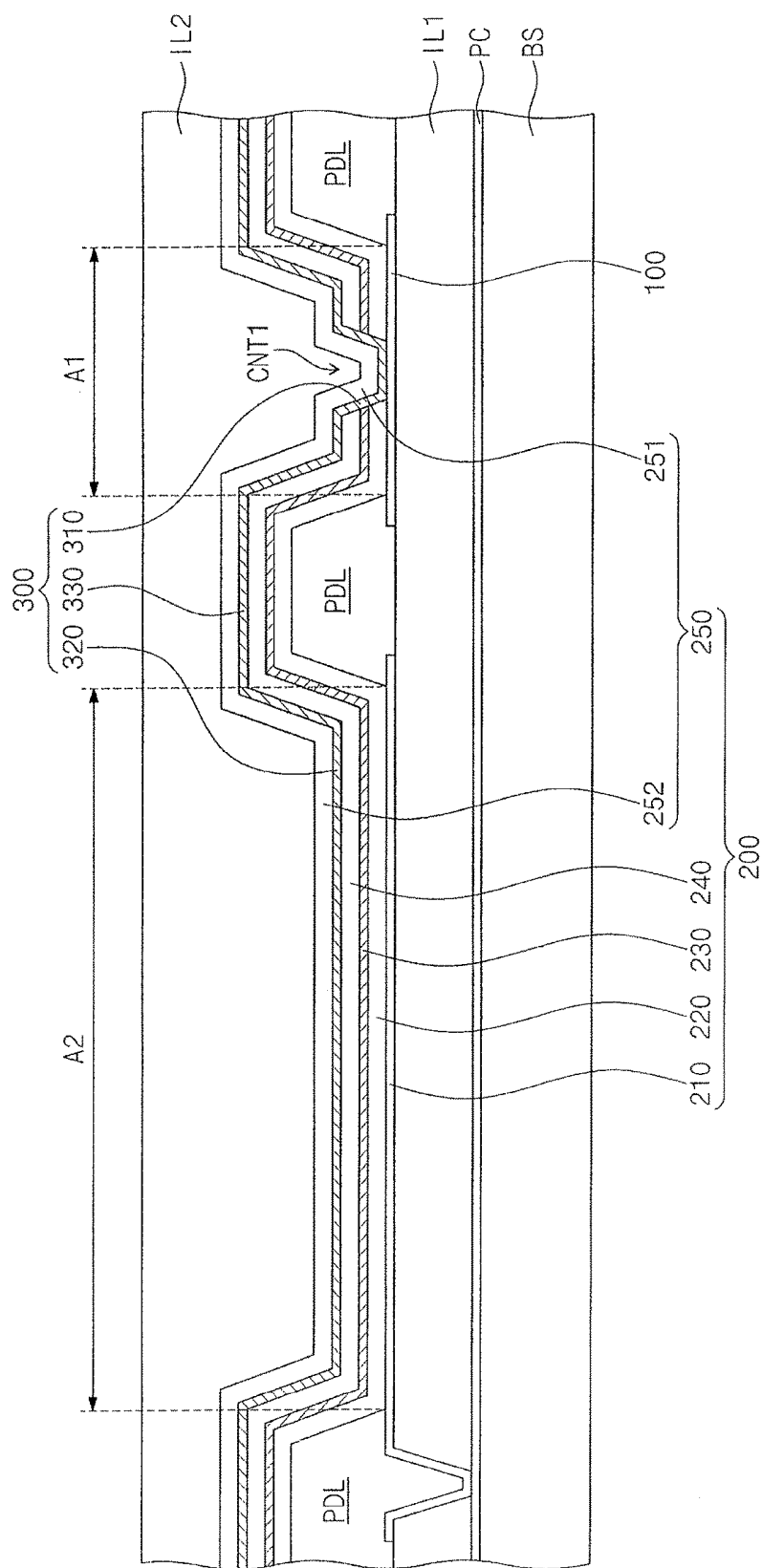


FIG. 9A

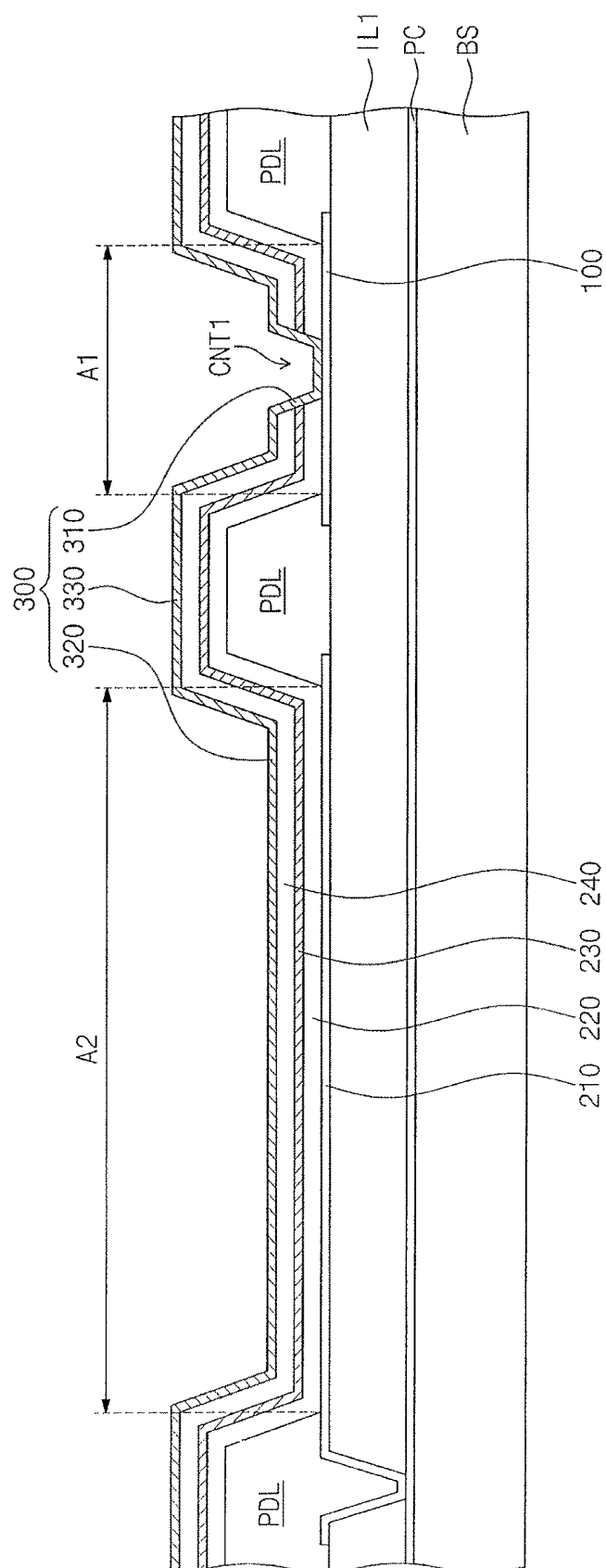


FIG. 9B

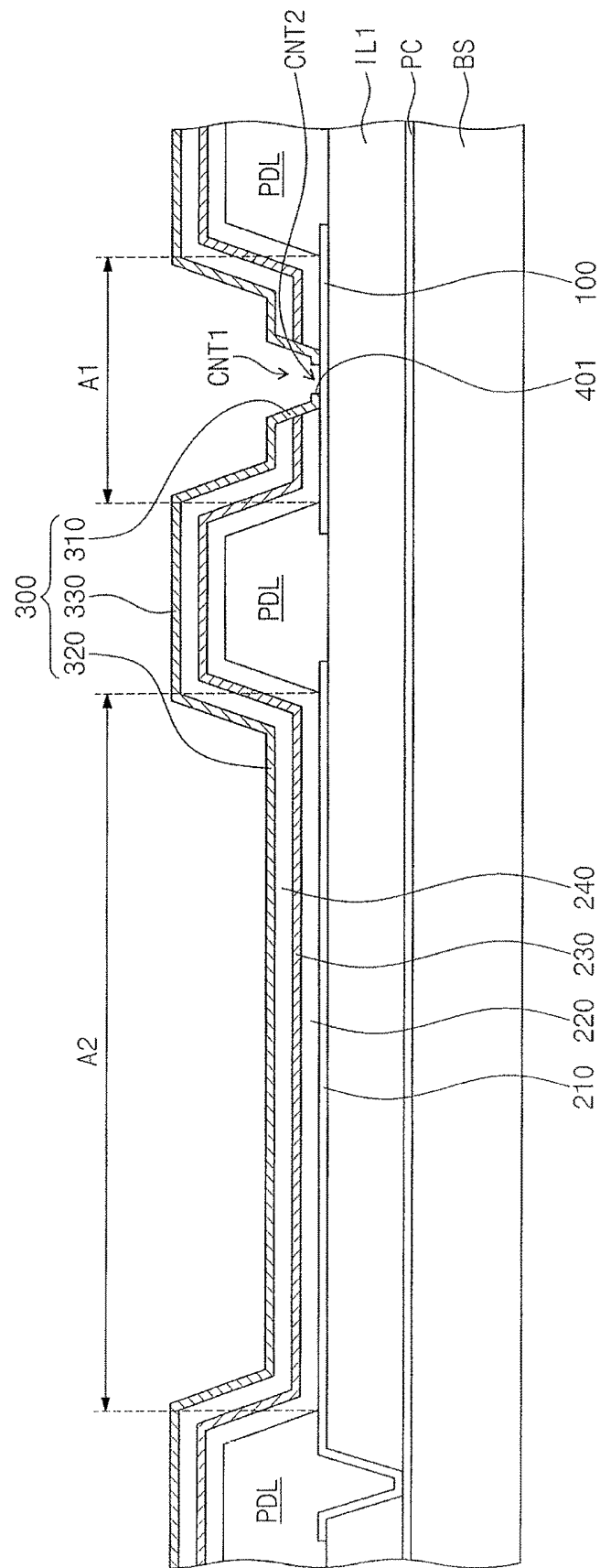
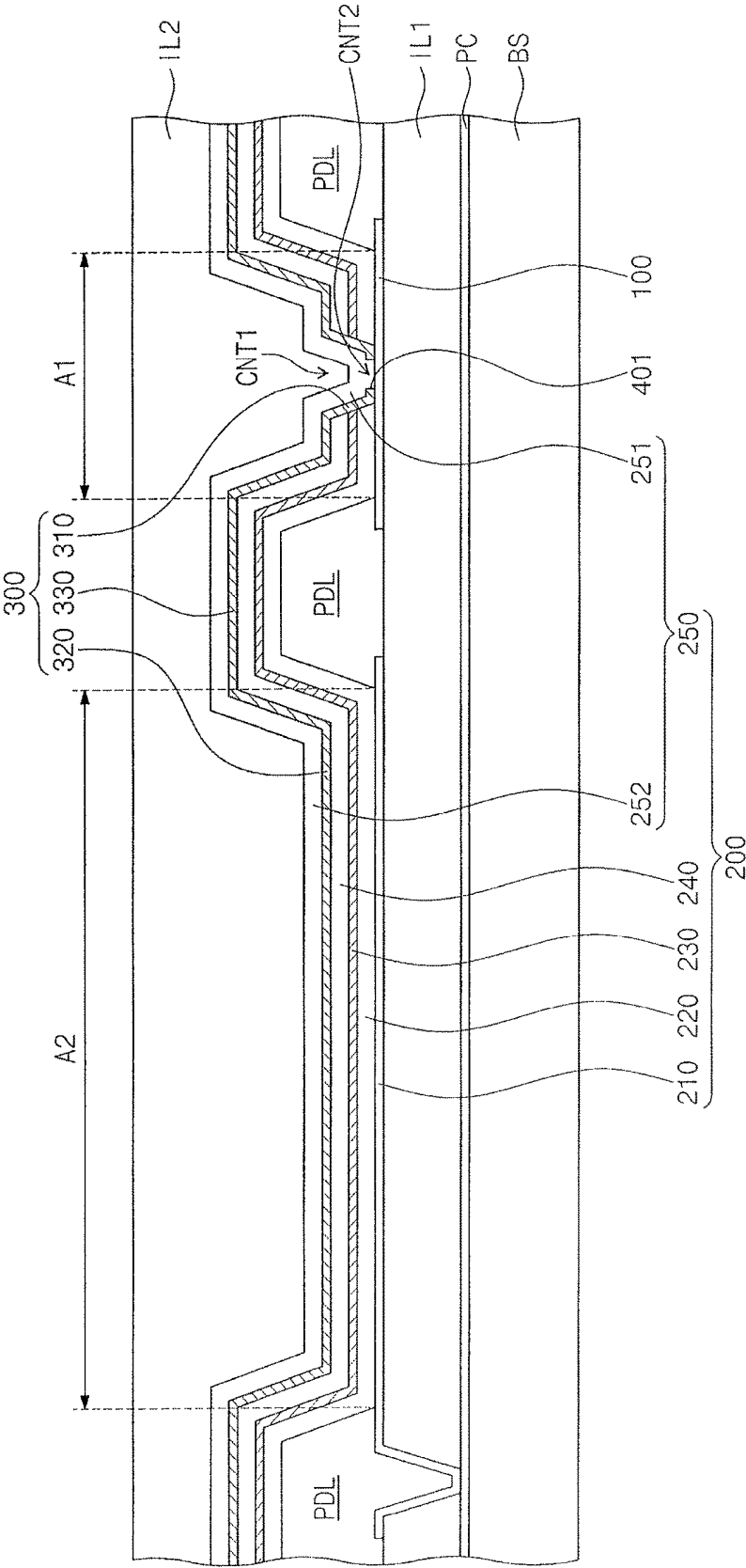


FIG. 9C



METHOD OF MANUFACTURING A DISPLAY PANEL CAPABLE OF PREVENTING A DEFECT IN LIGHT EMISSION OF AN ORGANIC LIGHT EMITTING ELEMENT

CROSS-REFERENCE TO RELATED APPLICATIONS

This is a divisional application based on pending application Ser. No. 15/646,362, filed Jul. 11, 2017, the entire contents of which is hereby incorporated by reference.

Korean Patent Application No. 10-2016-0090947, filed on Jul. 18, 2016, in the Korean Intellectual Property Office, and entitled: "Display Panel, Method of Manufacturing the Same, and Display Device Having the Same," is incorporated by reference herein in its entirety.

BACKGROUND

1. Field

The present disclosure relates to a display panel and a method of manufacturing the same. More particularly, the present disclosure relates to a display panel capable of preventing a defect in light emission of an organic light emitting element from occurring due to a lateral leakage current, a method of manufacturing the display panel, and a display device having the display panel.

2. Description of the Related Art

An organic light emitting device is a self-emissive device and has advantages of a wide viewing angle and a superior contrast ratio. In addition, the organic light emitting device has a fast response speed, a high brightness, and a low driving voltage. In general, the organic light emitting device includes an anode, a hole transport layer, a light emitting layer, an electron transport layer, and a cathode. The hole transport layer, the light emitting layer, the electron transport layer, and the cathode are sequentially stacked on the anode. The hole transport layer, the light emitting layer, and the electron transport layer are organic thin layers, each including an organic compound.

When different voltages are respectively applied to the anode and the cathode of the organic light emitting device, holes injected from the anode move to the light emitting layer through the hole transport layer, and electrons injected from the cathode move to the light emitting layer through the electron transport layer. The holes are recombined with the electrons in the light emitting layer to generate excitons, and the organic light emitting device emits light by the excitons that return to a ground state from an excited state.

SUMMARY

Embodiments provide a display panel including a base substrate, an auxiliary electrode disposed on the base substrate, a first electrode spaced apart from the auxiliary electrode when viewed in a plan view, a first light emitting unit disposed on the auxiliary electrode and the first electrode, an conductive thin film layer disposed on the first light emitting unit, a second light emitting unit disposed on the conductive thin film layer, an insulating layer including a first part disposed in a first contact hole defined through at least the first light emitting unit, the conductive thin film layer, and the second light emitting unit to expose the auxiliary electrode, and a second electrode including a first electrode

part and a second electrode part, the first electrode part being disposed on the first part and including at least a portion disposed in the first contact hole and the second electrode part extending from the first electrode part, overlapped with the first electrode when viewed in a plan view, and disposed on the second light emitting unit. A portion of the first part is disposed between the first electrode part and the conductive thin film layer to insulate the first electrode part from the conductive thin film layer.

The other portion of the first part is disposed between the first electrode part and the auxiliary electrode.

The other portion of the first part makes contact with the auxiliary electrode.

The portion of the first part makes contact with an exposing surface of the conductive thin film layer exposed through the first contact hole.

A second contact hole is defined in the other portion of the first part to expose at least a portion of an upper surface of the auxiliary electrode, and a portion of the first electrode part is disposed in the second contact hole defined in the insulating layer to make contact with the auxiliary electrode.

The insulating layer further includes a second part extending from the first part and disposed between the second light emitting unit and the second electrode.

The display panel further includes a pixel definition layer disposed between the auxiliary electrode and the first electrode when viewed in a plan view, and the insulating layer further includes a third part disposed on the pixel definition layer to connect the first and second parts.

The second part is overlapped with the first electrode when viewed in a plan view.

The insulating layer is spaced apart from the first electrode when viewed in a plan view.

The first light emitting unit generates a first light, and the second light emitting unit generates a light having a color different from a color of the first light.

The insulating layer has a resistance greater than a resistance of the conductive thin film layer.

The insulating layer has a thickness from about 1 nm to about 10 nm.

The insulating layer includes at least one of LiF and LiQ.

Embodiments also provide a method of manufacturing a display panel, including forming an auxiliary electrode in a first area defined in a base substrate, forming a first electrode in a second area defined in the base substrate and spaced apart from the first area when viewed in a plan view, forming a first light emitting unit on the first electrode, forming an conductive thin film layer on the first light emitting unit, forming a second light emitting unit on the conductive thin film layer, removing at least a portion of the first light emitting unit, the conductive thin film layer, and the second light emitting unit to form a first contact hole through which an upper surface of the auxiliary electrode is exposed, forming an insulating layer on an exposing surface of the conductive thin film layer, which is exposed through the first contact hole, and forming a second electrode on the insulating layer.

The method further includes removing a portion of the insulating layer to form a second contact hole, through which at least a portion of the upper surface of the auxiliary electrode is exposed, through the insulating layer.

The forming the second contact hole is performed after the forming the insulating layer and before the forming the second electrode.

The first light emitting unit, the conductive thin film layer, and the second light emitting unit are removed using a laser drilling method.

Embodiments also provide a display device including a display panel and a controller controlling the display panel. The display panel includes a base substrate, an auxiliary electrode disposed on the base substrate, a first electrode spaced apart from the auxiliary electrode when viewed in a plan view, a first light emitting unit disposed on the auxiliary electrode and the first electrode, a conductive thin film layer disposed on the first light emitting unit, a second light emitting unit disposed on the conductive thin film layer, an insulating layer including a first part disposed in a first contact hole defined through at least the first light emitting unit, the conductive thin film layer, and the second light emitting unit to expose the auxiliary electrode, and a second electrode including a first electrode part disposed in the first contact hole and disposed on the first part and a second electrode part extending from the first electrode part, overlapped with the first electrode when viewed in a plan view, and disposed on the second light emitting unit. A portion of the first part is disposed between the first electrode part and the conductive thin film layer to insulate the first electrode part from the conductive thin film layer.

The other portion of the first part is disposed between the first electrode part and the auxiliary electrode.

The other portion of the first part makes contact with the auxiliary electrode, and the portion of the first part makes contact with an exposing surface of the conductive thin film layer exposed through the first contact hole.

BRIEF DESCRIPTION OF THE DRAWINGS

Features will become apparent to those of ordinary skill in the art by describing in detail exemplary embodiments with reference to the attached drawings, in which:

FIG. 1 illustrates a plan view of a display device according to an exemplary embodiment of the present disclosure;

FIG. 2 illustrates a plan view of a display panel according to an exemplary embodiment of the present disclosure;

FIG. 3A illustrates a cross-sectional view along line I-I' in FIG. 2;

FIG. 3B illustrates an enlarged cross-sectional view of a first contact hole shown in FIG. 3A;

FIG. 3C illustrates an enlarged cross-sectional view of the first contact hole shown in FIG. 3A;

FIG. 3D illustrates a cross-sectional view of a display panel according to an exemplary embodiment of the present disclosure;

FIG. 4 illustrates a plan view of a display panel according to an exemplary embodiment of the present disclosure;

FIG. 5 illustrates a cross-sectional view along line II-II' in FIG. 2;

FIG. 6 illustrates a cross-sectional view of a display panel according to an exemplary embodiment of the present disclosure;

FIG. 7 illustrates a schematic cross-sectional view of an organic light emitting element according to an exemplary embodiment of the present disclosure;

FIGS. 8A to 8F illustrate cross-sectional views of stages in a method of manufacturing a display panel according to an exemplary embodiment; and

FIGS. 9A to 9C illustrate cross-sectional views of stages in a method of manufacturing a display panel according to an exemplary embodiment.

DETAILED DESCRIPTION

Example embodiments will now be described more fully hereinafter with reference to the accompanying drawings;

however, they may be embodied in different forms and should not be construed as limited to the embodiments set forth herein. Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey exemplary implementations to those skilled in the art.

The use of the terms first, second, etc. do not denote any order or importance, but rather the terms first, second, etc. are used to distinguish one element from another. It is to be understood that the singular forms “a,” “an,” and “the” include plural referents unless the context clearly dictates otherwise.

It will be further understood that the terms “includes” and/or “including”, when used in this specification, specify the presence of stated features, integers, steps, operations, elements, and/or components, but do not preclude the presence or addition of one or more other features, integers, steps, operations, elements, components, and/or groups thereof.

In the drawing figures, the dimensions of layers and regions may be exaggerated for clarity of illustration. It will also be understood that when a layer, i.e., an element, is referred to as being “on” another layer or substrate, it can be directly on the other layer or substrate, or intervening layers may also be present. In addition, it will also be understood that when a layer is referred to as being “between” two layers, it can be the only layer between the two layers, or one or more intervening layers may also be present. Like reference numerals refer to like elements throughout. Further, it will be understood that when an element or layer is referred to as being “connected to” or “coupled to” another element or layer, it can be directly connected or coupled to the other element or layer or intervening elements or layers may be present. In contrast, when an element is referred to as being “directly on,” “directly between,” “directly connected to,” “directly coupled to” another element or layer, there are no intervening elements or layers present.

Hereinafter, embodiments will be explained in detail with reference to the accompanying drawings.

FIG. 1 is a plan view showing a display device DD according to an exemplary embodiment of the present disclosure.

Referring to FIG. 1, the display device DD may include a display panel DP, a flexible printed circuit board FPC, and a printed circuit board PCB. The display panel DP displays an image through a display area DA. The display area DA is operated by a control signal and image data provided from the printed circuit board PCB.

The display panel DP includes gate lines GL1 to GLn, data lines DL1 to DLm, and sub-pixels SPX, which are arranged in the display area DA. The gate lines GL1 to GLn extend in a first direction DR1 and are arranged, e.g., spaced apart, in a second direction DR2. The data lines DL1 to DLm are insulated from the gate lines GL1 to GLn while crossing the gate lines. For instance, the data lines DL1 to DLm extend in the second direction DR2 and are arranged, e.g., spaced apart, in the first direction DR1. In the following descriptions, a direction substantially parallel to the first and second directions DR1 and DR2 may be referred to as a “horizontal direction”.

The display panel DP includes a non-display area NDA surrounding the display area DA when viewed in a plan view. The sub-pixels SPX are not arranged in the non-display area NDA, and the image is not displayed through the non-display area NDA. The non-display area NDA may be referred to as a “bezel” of the display device DD.

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Each of the sub-pixels SPX is connected to a corresponding gate line of the gate lines GL1 to GLn and a corresponding data line of the data lines DL1 to DLm. The sub-pixels SPX may be arranged in a matrix form along the first and second directions DR1 and DR2. Each sub-pixel SPX displays one of three primary colors of red, green, and blue colors. The colors displayed by the sub-pixels SPX are not be limited to red, green, and blue colors, and the sub-pixels SPX may display a second primary color of white, yellow, cyan, and magenta colors in addition to the red, green, and blue colors.

The sub-pixels SPX may form the pixel PX. As an example, four sub-pixels SPX may form one pixel PX, but the number of the sub-pixels SPX required to form one pixel PX is not be limited to four. That is, one pixel PX may include two, three, five, or more sub-pixels SPX.

The pixel PX serves as an element to display a unit image, and a resolution of the display panel DP is determined by the number of the pixels PX included in the display panel DP. FIG. 1 shows only one pixel PX, and the other pixels may have the same configurations as the one pixel PX. In the present exemplary embodiment, the display panel DP may be, but not limited to, an organic light emitting display panel, and each sub-pixel SPX may include an organic light emitting element.

The display panel DP may have, for example, a plate-like shape with a pair of short sides and a pair of long sides, which are respectively parallel to the first and second directions DR1 and DR2. In the present exemplary embodiment, the display panel DP may have various shapes. The display panel DP may have a shape curved in at least one direction when viewed in a cross-section, or the display panel DP may have at least one round-shaped edge when viewed in a plan view.

The flexible printed circuit board FPC connects the display panel DP and the printed circuit board PCB. FIG. 1 shows only one flexible printed circuit board FPC, but the flexible printed circuit board FPC may be provided in a plural number. The flexible printed circuit boards FPC may be arranged in an edge of the display panel along one direction. In the present exemplary embodiment, the number of the flexible printed circuit boards may vary.

As an example, the flexible printed circuit board FPC includes a driving chip DC. The driving chip DC is mounted in a tape carrier package (TCP) manner and includes a chip implemented as a data driver. The driving chip DC may further include a chip implemented as a gate driver. In addition, the gate driver may be disposed in the non-display area NDA.

The printed circuit board PCB includes a controller to control the display panel DP. The controller receives input image signals and converts a data format of the input image signals to a data format appropriate to an interface and a driving mode of the data driver, the gate driver, and the display panel DP to generate the image data. The controller outputs the image data and the control signal. The image data include information with respect to the image displayed in the display area DA.

The data driver receives the image data and the control signal. The data driver converts the image data to data voltages in response to the control signal and applies the data voltages to the data lines DL1 to DLm. The data voltages may be analog voltages corresponding to the image data.

Various electronic devices may be mounted on the printed circuit board PCB to implement the controller. For instance, the printed circuit board PCB may include a passive device, e.g., a capacitor, a resistor, etc., an active device, e.g., a

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microprocessor including an integrated circuit, a memory chip, etc., and lines connecting them.

The display panel DP may further include an auxiliary electrode 100. The auxiliary electrode 100 may be disposed between the sub-pixels SPX when viewed in a plan view.

The auxiliary electrode 100 may have, for example, a grid shape. The auxiliary electrode 100 includes a plurality of first extension parts 100_a and a plurality of second extension parts 100_b. The first extension parts 100_a extend in the first direction DR1 and are arranged in the second direction DR2. The second extension parts 100_b extend in the second direction DR2 and are arranged in the first direction DR1. The first and second extension parts 100_a and 100_b may be disposed every one sub-pixel SPX along the first and second directions DR1 and DR2, e.g., each of the first extension parts 100_a may be disposed along corresponding rows of sub-pixel SPX in a one-to-one correspondence, and each of the second extension parts 100_b may be disposed along corresponding columns of sub-pixels SPX in a one-to-one correspondence. However, embodiments are not limited thereto or thereby, e.g., the first and second extension parts 100_a and 100_b may be disposed every two sub-pixels SPX along the first and second directions DR1 and DR2.

The auxiliary electrode 100 may prevent an IR-drop from occurring in the display panel DP. The IR-drop will be described in detail later.

FIG. 2 is a plan view showing a display panel according to an exemplary embodiment of the present disclosure, FIG. 3A is a cross-sectional view taken along line I-I' in FIG. 2, FIG. 3B is an enlarged cross-sectional view showing a first contact hole in FIG. 3A, and FIG. 3C is an enlarged cross-sectional view showing the first contact hole in FIG. 3A.

Referring to FIG. 2, each of the pixels PX may include first, second, third, and fourth sub-pixels SPX1, SPX2, SPX3, and SPX4. The first to fourth sub-pixels SPX1 to SPX4 correspond to an embodiment of the sub-pixels SPX shown in FIG. 1.

In the present exemplary embodiment, the first, second, third, and fourth sub-pixels SPX1, SPX2, SPX3, and SPX4 respectively correspond to red, green, blue, and white sub-pixels. Each of the first to fourth sub-pixels SPX1 to SPX4 may have, e.g., a substantially quadrangular shape.

In the present exemplary embodiment, the display panel DP may include a pixel definition layer PDL disposed between the first to fourth sub-pixels SPX1 to SPX4. The pixel definition layer PDL may define a boundary between the first to fourth sub-pixels SPX1 to SPX4 and a boundary between the pixels PX.

In the present exemplary embodiment, a first contact hole CNT1 is defined through the display panel DP. The first contact hole CNT1 is defined in an area in which the first and second extension parts 100_a and 100_b cross each other.

Referring to FIG. 3A, the display panel DP may include a base substrate BS, a pixel circuit layer PC, a first insulating layer IL1, an organic light emitting element 200, an insulating layer 300, and a second insulating layer IL2. The base substrate BS may be transparent and may include, e.g., a rigid glass or a flexible polymer.

The pixel circuit layer PC may be disposed on the base substrate BS. The pixel circuit layer PC may include a circuit to drive the organic light emitting element 200 and at least two transistors. The pixel circuit layer PC may include, e.g., a switching transistor turned on in response to a gate signal applied thereto to transmit the data voltage and a driving

transistor applying a driving current corresponding to the data voltage from the switching transistor to the organic light emitting element **200**.

The first insulating layer **IL1** may be disposed on the pixel circuit layer **PC**. The first insulating layer **IL1** may include a contact hole defined therethrough to expose a portion of the pixel circuit layer **PC**. The first insulating layer **IL1** has a single- or multi-layer structure of an organic material or an inorganic material.

In the present exemplary embodiment, the organic light emitting element **200** may include a first electrode **210**, a first light emitting unit **220**, a conductive thin film layer **230**, a second light emitting unit **240**, and a second electrode **250**.

In the present exemplary embodiment, the first electrode **210** may be disposed on the first insulating layer **ILL**. For example, a first end of the first electrode **210** makes contact with the pixel circuit layer **PC** through the contact hole in the first insulating layer **IL1** to receive the driving current from the pixel circuit layer **PC**.

The base substrate **BS** includes a first area **A1** and a second area **A2** spaced apart from the first area **A1** in a horizontal direction. A second end of the first electrode **210** extends from the first electrode **210** and is disposed in the second area **A2**.

The auxiliary electrode **100** is disposed in the first area **A1**. The auxiliary electrode **100** includes a conductive material. The auxiliary electrode **100** may be a transparent electrode, a semi-transparent electrode, or a non-transparent electrode (or a reflective electrode). In addition, the auxiliary electrode **100** may have a single-layer structure of a single material or plural different materials or a multi-layer structure of layers formed of different materials.

In the present exemplary embodiment, the pixel definition layer **PDL** is disposed on the auxiliary electrode **100** and the first electrode **210**. The pixel definition layer **PDL** covers an edge of the auxiliary electrode **100** and exposes a center portion of the auxiliary electrode **100**. A portion of the pixel definition layer **PDL** may be disposed between the first and second areas **A1** and **A2** when viewed in a plan view. The first area **A1** may be defined to correspond to the center portion of the auxiliary electrode **100**.

The pixel definition layer **PDL** may cover an edge of the first electrode **210** and expose a center portion of the first electrode **210**. The second area **A2** may be defined to correspond to the exposed center portion of the first electrode **210**.

In the present exemplary embodiment, the first light emitting unit **220** is disposed on the pixel definition layer **PDL**, the first electrode **210**, and the auxiliary electrode **100**. The first light emitting unit **220** generates, e.g., a first light having a first color. The first light emitting unit **220** includes a plurality of organic layers.

In the present exemplary embodiment, the conductive thin film layer **230** may be disposed on the first light emitting unit **220**. The conductive thin film layer **230** is disposed between the first and second light emitting units **220** and **240** to provide electric charges (electrons and/or holes) to the first and second light emitting units **220** and **240** and to control a balance of the electric charges.

In the present exemplary embodiment, the second light emitting unit **240** may be disposed on the conductive thin film layer **230**. The second light emitting unit **240** generates, e.g., a second light having a second color. The second light emitting unit **240** includes a plurality of organic layers.

In the present exemplary embodiment, the organic light emitting element **200** may be, but is not limited to, a white

organic light emitting element. A color obtained by mixing the first and second colors may be white, and the first and second colors may have a complementary color relationship with each other. The first and second lights may be mixed with each other to generate white light. For example, the first and second colors may be respectively blue and yellow colors, but they are not limited thereto or thereby, e.g., the first and second colors may be respectively red and green colors.

The second electrode **250** may be disposed on the insulating layer **300**. The second electrode **250** includes a first electrode part **251** disposed in the first area **A1** and a second electrode part **252** extending from the first electrode part **251** and disposed in the second area **A2**. In more detail, the first electrode part **251** and the second electrode part **252** are respectively overlapped with the auxiliary electrode **100** and the first electrode **210** when viewed in a plan view.

The second electrode **250** is disposed over the entire surface of the base substrate **BS**. Accordingly, the IR-drop occurs in the second electrode **250** along the horizontal direction, and a brightness of the pixel **PX** becomes different in accordance with a position of the display panel **DP**. To prevent the IR-drop from occurring, the second electrode **250** may be connected to the auxiliary electrode **100**. Since the auxiliary electrode **100** is connected to the second electrode **250** through a first part **310** of the insulating layer **300**, the IR-drop occurring in the second electrode **250** may be prevented from occurring or may be reduced.

In the present exemplary embodiment, the insulating layer **300** is disposed on the second light emitting unit **240**, first, second, and third exposing surfaces **221**, **231**, and **241**, and a portion of the auxiliary electrode **100**. In the present exemplary embodiment, the insulating layer **300** includes the first part **310**, a second part **320**, and a third part **330**.

In detail, at least a portion of the first part **310**, i.e., a first portion of the first part **310**, is disposed, e.g., conformally along sidewalls, in the first contact hole **CNT1**. Referring to FIGS. 3B and 3C, the first contact hole **CNT1** is defined in the first area **A1** and is disposed above the auxiliary electrode **100**. The first contact hole **CNT1** is defined through the first light emitting unit **220**, the conductive thin film layer **230**, and the second light emitting unit **240** to expose the auxiliary electrode **100**. In FIGS. 3B and 3C, some elements are not shown for the convenience of explanation of the first contact hole **CNT1** and the first part **310**. For instance, the insulating layer **300** and layers disposed above the insulating layer **300** are not shown in FIG. 3C.

In the following descriptions, the expression "a contact hole is defined in a layer" means that a space obtained by partially removing the layer is defined as the contact hole. Accordingly, the first contact hole **CNT1** may be defined by an empty space (an area hatched with dots in FIGS. 3B and 3C) formed by partially removing the first light emitting unit **220**, the conductive thin film layer **230**, and the second light emitting unit **240**.

At least a portion of an upper surface of the auxiliary electrode **100**, the first exposing surface **221** of the first light emitting unit **220**, the second exposing surface **231** of the conductive thin film layer **230**, and the third exposing surface **241** of the second light emitting unit **240** are exposed through the first contact hole **CNT1**. Since the first portion of the first part **310** is disposed in the first contact hole **CNT1**, the first portion of the first part **310** may be disposed only in an area surrounded by the first, second, and third exposing surfaces **221**, **231**, and **241**.

The first portion of the first part **310** is disposed between the conductive thin film layer **230** and the first electrode part

251. A lower surface of the first portion of the first part 310 makes contact with the first, second, and third exposing surfaces 221, 231, and 241, and an upper surface of the first portion 310 makes contact with the first electrode part 251.

In the present exemplary embodiment, a second portion of the first part 310 is disposed between the first electrode part 251 and the auxiliary electrode 100 to electrically connect the first electrode part 251 to the auxiliary electrode 100. A lower surface of the second portion of the first part 310 makes contact with the auxiliary electrode 100. For example, referring to FIG. 3A, the second portion of the first part 310 is a portion extending in parallel to the base substrate BS, i.e., on a bottom of the first contact hole CNT1, on the auxiliary electrode 100, and the first portion of the first part 310 is a portion extending from the second portion along sidewalls of the first contact hole CNT1.

In the present exemplary embodiment, the second part 320 is disposed in the second area A2. The second part 320 is disposed on the second electrode part 252 and disposed between the second light emitting unit 240 and the second electrode part 252 in the second area A2.

In the present exemplary embodiment, the third part 330 is disposed between the first and second parts 310 and 320 when viewed in a plan view and connects the first and second parts 310 and 320. The third part 330 is disposed on the pixel definition layer PDL.

The insulating layer 300 prevents the lateral leakage current from flowing through the conductive thin film layer 230. If the insulating layer 300 were to be omitted, the conductive thin film layer 230 would directly contact the first electrode part 251 in the first contact hole CNT1, causing a first voltage applied to the first electrode part 251 to be applied to the conductive thin film layer 230, thereby causing lateral leakage current through the conductive thin film layer 230 in the first contact hole CNT1. Accordingly, the lateral leakage current could pass through the first light emitting unit 220. In addition, a leakage voltage could be applied in the second area A2 due to the lateral leakage current. The leakage voltage may be voltage obtained by voltage-dividing the voltage applied in the first contact hole CNT1 along a path of the lateral leakage current. The leakage voltage is greater than the voltage applied to the first electrode 210 and smaller than the first voltage.

If lateral leakage current and leakage voltage are applied in the second areas A2, light emission of the light emitted from the first light emitting unit 220 may be poor (hereinafter, referred to as a "poor light emission"). For instance, if lateral leakage current and leakage voltage are applied in the second areas A2, e.g., when the insulating layer 300 is omitted, when voltage corresponding to zero (0) grayscale level is applied to the first electrode 210, the first light emitting unit 220 may emit light or generate light corresponding to a grayscale level different from the grayscale level of the voltage applied to the first electrode 210.

In contrast, according to the present exemplary embodiment, the insulating layer 300 may insulate the conductive thin film layer 230 from the second electrode 250, thereby preventing the lateral leakage current and the leakage voltage between the conductive thin film layer 230 and the first electrode part 251, which in turn, prevents or substantially minimizes poor light emission from occurring in the organic light emitting element 200. In more detail, the first portion of the insulating layer 300 along a sidewall of the first contact hole CNT1 may, e.g., completely or partially, insulate the conductive thin film layer 230 from the second electrode 250.

In the case that the insulating layer 300 completely insulates the conductive thin film layer 230 from the second electrode 250, the lateral leakage current does not flow to the conductive thin film layer 230 from the first electrode part 251, and the leakage voltage is not applied to the first part 310. In the case that the insulating layer 300 partially insulates the conductive thin film layer 230 from the second electrode 250, a lateral leakage current equal to or smaller than a critical current may flow, and leakage voltage equal to or smaller than a critical voltage may be applied to the second part 320. When the leakage voltage is smaller than the critical voltage and the lateral leakage current is smaller than the critical current, the first light emitting unit 220 may not emit the light, e.g., may not emit light corresponding to voltage and/or current smaller than respective critical values.

The insulating layer 300 has a resistance determined such that poor light emission is prevented. The resistance of the insulating layer 300 is greater than a resistance of the conductive thin film layer 230. The insulating layer 300 has a thickness determined such that the first electrode part 251 is electrically connected to the auxiliary electrode 100 and the conductive thin film layer 230 is insulated from the first electrode part 251.

The thickness of the insulating layer 300 is in a range from about 1 nm to about 10 nm. The insulating layer 300 is required to have the above indicated thickness, and thus the insulating layer 300 may have an insulating function in the first area A1. In addition, it is preferred that the insulating layer 300 has the above indicated thickness to perform an electron injection/transport function or a hole injection/transport function in the second area A2. These will be described in detail with reference to FIG. 7. According to the above, in the present exemplary embodiment, the insulating layer 300 insulates the conductive thin film layer 230 from the second electrode 250, and thus poor light emission of the organic light emitting element 200 due to the lateral leakage current may be prevented from occurring, and the organic light emitting element 200 may be stably driven.

Each of the first and second electrodes 210 and 250 includes a conductive material. In more detail, each of the first and second electrodes 210 and 250 is a transparent electrode, a semi-transparent electrode, or a non-transparent electrode (or a reflective electrode). In addition, the first and second electrodes 210 and 250 may have a single-layer structure of a single material or plural different materials or a multi-layer structure of layers formed of different materials.

In the case that each of the first and second electrodes 210 and 250 is a transparent electrode or a semi-transparent electrode, each of the first and second electrodes 210 and 250 may include, for example, Li, Ca, LiF/Ca, LiF/Al, Al, Mg, BaF, Ba, Ag, a compound thereof, or a mixture thereof, e.g., a mixture of Ag and Mg, each which is optically thin, or a transparent metal oxide, e.g., indium tin oxide (ITO), indium zinc oxide (IZO), zinc oxide (ZnO), indium tin zinc oxide (ITZO), Mo, Ti, etc. In the case that each of the first and second electrodes 210 and 250 is a reflective electrode, each of the first and second electrodes 210 and 250 may include, e.g., Ag, Mg, Cu, Al, Pt, Pd, Au, Ni, Nd, Ir, Cr, Li, Ca, LiF/Ca, LiF/Al, Mo, Ti, a compound thereof, or a mixture thereof, e.g., a mixture of Ag and Mg, each which is optically thick.

In the present exemplary embodiment, the organic light emitting element 200 may be a rear surface light emitting type or a front surface light emitting type. In the case that the organic light emitting element 200 is a rear surface light

emitting type, the first electrode **210** is provided as a transparent or semi-transparent electrode, and the second electrode **250** is a reflective electrode. In this case, white light exits to the outside through the first electrode **210**. In the case that the organic light emitting element **200** is a front surface light emitting type, the first electrode **210** is provided as a reflective electrode, the second electrode **250** is a transparent or semi-transparent electrode, and accordingly, white light exits to the outside through the second electrode **250**.

As an example, the organic light emitting element **200** may have a non-inverted structure or an inverted structure. When the organic light emitting element **200** has a non-inverted structure, the first electrode **210** is an anode, the second electrode **250** is a cathode, and a voltage applied to the first electrode **210** is greater than a voltage applied to the second electrode **250**. On the contrary, when the organic light emitting element **200** has an inverted structure, the first electrode **210** is the cathode, the second electrode **250** is the anode, and the voltage applied to the first electrode **210** is smaller than the voltage applied to the second electrode **250**.

FIG. 3D is a cross-sectional view showing a display panel according to an exemplary embodiment of the present disclosure. The display panel DP in FIG. 3D is substantially the same as the display panel DP in FIG. 3A, with the exception of the first contact hole and the first part extending deeper than those in FIG. 3A.

Referring to FIG. 3D, the pixel circuit layer PC includes a transistor TR. The transistor TR includes a gate electrode GE, a source electrode SE, a drain electrode DE, and a semiconductor layer SL. The semiconductor layer SL is disposed on the base substrate BS. A first transistor insulating layer TRI1 is disposed on the semiconductor layer SL. A second transistor insulating layer TRI2 is disposed above the first transistor insulating layer TRI1. The source electrode SE and the drain electrode DE are disposed on the second transistor insulating layer TRI2 and spaced apart from each other.

The source electrode SE is connected to one end of the semiconductor layer SL through a contact hole defined through the first and second transistor insulating layers TRI1 and TRI2, and the drain electrode DE is connected to the other end of the semiconductor layer SL through a contact hole defined through the first and second transistor insulating layers TRI1 and TRI2. The transistor TR applies voltage applied to the source electrode SE to the first electrode **210** through the drain electrode DE in response to a control signal applied to the gate electrode GE.

The auxiliary electrode **100** is disposed between the first insulating layer IL1 and the second transistor insulating layer TRI2, and the first insulating layer IL1 includes an intermediate contact hole CNT_M defined therethrough to expose the auxiliary electrode **100**. That is, the upper surface of the auxiliary electrode **100** is exposed through the intermediate contact hole CNT_M. Portions of the first and second light emitting units **220** and **240** and the conductive thin film layers **230**, which are disposed in the first area A1, are disposed in the intermediate contact hole CNT_M.

The first contact hole CNT1 is defined through the portions of the first and second light emitting units **220** and **240** and the conductive thin film layers **230**, which are disposed in the intermediate contact hole CNT_M. The upper surface of the auxiliary electrode **100** is exposed through the first contact hole CNT1. For example, as illustrated in FIG. 3D, the first and intermediate contact holes CNT1 and CNT_M may be in fluid communication with each other, e.g., portions of the first light emitting unit **220** may extend along

sidewalls of the first contact hole CNT1 and continuously extend along sidewall of the intermediate contact hole CNT_M. For example, as further illustrated in FIG. 3D, the intermediate contact hole CNT_M may be between the first contact hole CNT1 and sidewalls of the first insulating layer IL1. e.g., the intermediate contact hole CNT_M may extend radially from the first contact hole CNT1 toward the sidewalls of the first insulating layer IL1.

In the present exemplary embodiment, the first part **310** of the insulating layer **300** is disposed in the first contact hole CNT1. At least the portion of an upper surface of the auxiliary electrode **100**, the first exposing surface **221** of the first light emitting unit **220**, the second exposing surface **231** of the conductive thin film layer **230**, and the third exposing surface **241** of the second light emitting unit **240** are exposed through the first contact hole CNT1. Since the first part **310** is disposed in the first contact hole CNT1, the first part **310** may be disposed only in the area surrounded by the first, second, and third exposing surfaces **221**, **231**, and **241** and the first electrode part **251**.

The first portion of the first part **310**, e.g., on sidewalls of the first contact hole CNT1, is disposed between the conductive thin film layer **230** and the first electrode part **251**. A lower surface of the portion of the first part **310** makes contact with the first, second, and third exposing surfaces **221**, **231**, and **241**, and an upper surface of the first portion **310** makes contact with the first electrode part **251**. In the present exemplary embodiment, the second portion of the first part **310**, e.g., on a bottom of the first contact hole CNT1, is disposed between the first electrode part **251** and the auxiliary electrode **100** to electrically connect the first electrode part **251** to the auxiliary electrode **100**. A lower surface of the second portion of the first part **310** makes contact with the auxiliary electrode **100**. In addition, according to another embodiment, the auxiliary electrode **100** may be disposed between the first and second transistor insulating layers TRI1 and TRI2. The first contact hole CNT1 is defined in the first transistor insulating layer TRI1 to expose the upper surface of the auxiliary electrode **100**, and the first portion **310** may be disposed in the first contact hole CNT1.

FIG. 4 is a plan view showing a display panel according to an exemplary embodiment of the present disclosure, and FIG. 5 is a cross-sectional view taken along line II-II' in FIG. 2. The display panel DP in FIGS. 4 and 5 is substantially the same as the display panel DP shown in FIGS. 2-3, except for a second contact hole CNT2 and the conductive thin film layer. Thus different features of the second contact hole CNT2 and the conductive thin film layer will be mainly described, and details of the others will be omitted.

Referring to FIG. 4, the second contact hole CNT2 may be further defined in the display panel DP. The second contact hole CNT2 may be defined in the first contact hole CNT1 when viewed in a plan view.

Referring to FIG. 5, the second contact hole CNT2 is defined in the first area A1 above the auxiliary electrode **100**. The second contact hole CNT2 is defined through the insulating layer **300**. In more detail, the second contact hole CNT2 is defined in the first part **310**, and at least a portion of an upper surface of the auxiliary electrode **100** and a fourth exposing surface **301** of the insulating layer **300** are exposed through the second contact hole CNT2.

In the present exemplary embodiment, at least a portion of the first electrode part **251** is disposed in the second contact hole CNT2 and makes contact with the portion of the auxiliary electrode **100** exposed through the second contact hole CNT2. As described above, since the second electrode **250** is directly connected to the auxiliary electrode **100**, a

voltage drop does not occur between the second electrode **250** and the auxiliary electrode **100**. Accordingly, the IR-drop may be effectively prevented, and a voltage-current characteristic of the organic light emitting element **200** may be improved.

FIG. **6** is a cross-sectional view showing a display panel according to an exemplary embodiment of the present disclosure. The display panel DP in FIG. **6** is substantially the same as the display panel DP shown in FIG. **5**, except for the insulating layer. Thus different features of the insulating layer will be mainly described, and details of the others will be omitted.

Referring to FIG. **6**, the insulating layer **300** is not disposed in the second area A2. The insulating layer **300** is disposed spaced apart from the second area A2 without being overlapped with the second area A2 when viewed in a plan view. In other words, the second and third parts **320** and **330** may be omitted.

In the present exemplary embodiment, the insulating layer **300** is not disposed between organic layers of the organic light emitting element **200** in the second area A2. Accordingly, the insulating layer **300** does not exert an influence on the balance of electric charge and the voltage-current characteristic of the organic light emitting element **200**. Thus, a design of the organic light emitting element **200** to maintain the electric charge balance and a design of the insulating layer **300** to prevent the lateral leakage current from occurring may be independently performed.

FIG. **7** is a schematic cross-sectional view of the organic light emitting element **200**.

Referring to FIG. **7**, the first light emitting unit **220** includes a first hole control layer HCL1, a first light emitting layer EML1, and a first electron control layer ECL1. The second light emitting unit **240** includes a second hole control layer HCL2, a second light emitting layer EML2, and a second electron control layer ECL2.

The first and second light emitting layers EML1 and EML2 are disposed between the first electrode **210** and the second electrode **250**. In the present exemplary embodiment, each of the first and second light emitting layers EML1 and EML2 includes a host material and a dopant material. Each of the first and second light emitting layers EML1 and EML2 is formed by applying a fluorescent material or a phosphorescent material to the host material.

As the host, for example, Alq3(tris(8-hydroxyquinolino)aluminum), CBP(4,4'-bis(N-carbazolyl)-1,1'-biphenyl), PVK(poly(n-vinylcarbazole), ADN(9,10-di(naphthalene-2-yl)anthracene), TCTA(4,4',4''-Tris(carbazol-9-yl)-triphenylamine), TPBi(1,3,5-tris(N-phenylbenzimidazole-2-yl)benzene), TBADN(3-tert-butyl-9,10-di(naphth-2-yl)anthracene), DSA(distyrylarylene), CDBP(4,4'-bis(9-carbazolyl)-2,2''-dimethyl-biphenyl), MADN(2-Methyl-9,10-bis(naphthalen-2-yl)anthracene) may be used. However, embodiments are not limited thereto or thereby.

Colors of the light emitting layers may be determined by a combination of the host material and the dopant material. For instance, when the light emitting layers emit red light, the light emitting layers may include a fluorescent material containing, e.g., PBD:Eu(DBM)3(Phen)(tris(dibenzoylmethanato)phenanthroline europium) or Perylene. When the light emitting layers emit the red light, the dopant included in the organic light emitting layers may be a metal complex, e.g., PIQIr(acac)(bis(1-phenylisoquinoline)acetylacetonate iridium), PQIr(acac)(bis(1-phenylquinoline)acetylacetonate iridium), PQIr(tris(1-phenylquinoline)iridium), PtOEP(octaethylporphyrin platinum), etc., or organometallic complex.

When the light emitting layers emit green light, the light emitting layers may include a fluorescent material containing, e.g., Alq3(tris(8-hydroxyquinolino)aluminum). When the light emitting layers emit the green light, the dopant included in the light emitting layers may be a metal complex, e.g., Ir(ppy)3(fac-tris(2-phenylpyridine)iridium), or organometallic complex.

When the light emitting layers emit blue light, the light emitting layers may include a fluorescent material including, e.g., any one from the groups consisting of spiro-DPVBi, spiro-6P, DSB(distyryl-benzene), DSA(distyryl-arylene), PFO(Polyfluorene)-based polymer, and PPV(poly(p-phenylene vinylene)-based polymer. When the light emitting layers emits blue light, the dopant included in the light emitting layers may be a metal complex, e.g., (4,6-F2ppy)2Irrpic, or organometallic complex.

The first light emitting layer EML1 generates light having a wavelength shorter than a wavelength of a light generated by the second light emitting layer EML2. As described above, the first light may be the blue light and have a wavelength range equal to or greater than about 450 nm and equal to or smaller than about 595 nm. As described above, the second light may be the yellow light and have a wavelength range equal to or greater than about 570 nm and equal to or smaller than about 590 nm.

Meanwhile, the first and second light emitting layers EML1 and EML2 may be designed to generate lights having various colors according to embodiments. The first and second light emitting layers EML1 and EML2 may be formed by various methods, e.g., a vacuum deposition method, a spin coating method, a cast method, an LB (Langmuir-Blodgett) method, an inkjet printing method, a laser printing method, an LITI (Laser Induced Thermal Imaging) method, etc.

The conductive thin film layer **230** is disposed between the first and second light emitting layers EML1 and EML2 to improve a current efficiency and a light efficiency of the organic light emitting element **200**. When voltage is applied to the conductive thin film layer **230**, the conductive thin film layer **230** generates electric charges by a complex formation due to oxidation-reduction reaction.

In the present exemplary embodiment, the conductive thin film layer **230** may include first and second conductive thin film layers **231** and **232** sequentially stacked. The first and second conductive thin film layers **231** and **232** may be respectively N-type and P-type conductive thin film layers. The N-type conductive thin film layer may include an alkali metal, e.g., Li, Na, K, Cs, or the like, or an organic layer doped with an alkali earth metal, e.g., Mg, Sr, Ba, Ra, or the like, but it should not be limited thereto or thereby. The P-type conductive thin film layer may include an organic layer with a P-type dopant, but it should not be limited thereto or thereby.

The first hole control layer HCL1 is disposed between the first electrode **210** and the first light emitting layer EML1. The second hole control layer HCL2 is disposed between the electric charge layer **230** and the second light emitting layer EML2.

When the first electrode **210** is an anode electrode layer, holes injected from the first electrode **210** are provided to the first light emitting layer EML1 through the first hole control layer HCL1. The holes generated by the conductive thin film layer **230** are provided to the second light emitting layer EML2 through the second hole control layer HCL2.

Each of the first and second hole control layers HCL1 and HCL2 may correspond to at least one of a hole injection area, a hole transport area, a buffer area, and an electron

block area. Each of the first and second hole control layers HCL1 and HCL2 may have a single-layer structure of a single material or plural different materials or a multi-layer structure of layers formed of different materials.

For instance, each of the first and second hole control layers HCL1 and HCL2 may include at least one of a hole injection layer corresponding to the hole injection layer, a hole transport layer corresponding to the hole transport area, and a single layer having a hole injection function and a hole transport function.

Each of the first and second hole control layers HCL1 and HCL2 may include at least one of a hole injection material and a hole transport material. The hole injection material and the hole transport material may be known materials.

The hole transport material may include, but not limited to, e.g., carbazole-based derivatives, e.g., n-phenyl carbazole, polyvinyl carbazole, etc., fluorine-based derivatives, triphenylamine-based derivatives, e.g., TPD(N,N'-bis(3-methylphenyl)-N,N'-diphenyl-[1,1'-biphenyl]-4,4'-diamine), TCTA(4,4',4''-tris(N-carbazolyl)triphenylamine), etc., NPB(N,N'-di(1-naphthyl)-N,N'-diphenylbenzidine), or TAPC(4,4'-Cyclohexylidene bis[N,N-bis(4-methylphenyl)benzenamine]). The hole injection material may include, but not limited to, at least one of a phthalocyanine compound such as copper phthalocyanine, DNTPD(N,N'-diphenyl-N,N'-bis-[4-(phenyl-m-tolyl-amino)-phenyl]-biphenyl-4,4'-diamine), m-MTDATA(4,4',4''-tris(3-methylphenylphenylamino)triphenylamine), TDATA(4,4',4''-Tris(N,N-diphenylamino)triphenylamine), 2TNATA(4,4',4''-tris{N-(2-naphthyl)-N-phenylamino}-triphenylamine), PEDOT/PSS(Poly(3,4-ethylenedioxythiophene)/Poly(4-styrenesulfonate), PANI/DBSA(Polyaniline/Dodecylbenzenesulfonic acid), PANI/CSA(Polyaniline/Camphor sulfonic acid), PANI/PSS((Polyaniline)/Poly(4-styrenesulfonate), etc.

Each of the first and second hole control layers HCL1 and HCL2 may be formed by similar process of forming the first and second light emitting layers EML1 and EML2. For instance, each of the first and second hole control layers HCL1 and HCL2 may be formed by various methods, e.g., a vacuum deposition method, a spin coating method, a cast method, an LB (Langmuir-Blodgett) method, an inkjet printing method, a laser printing method, an LITI (Laser Induced Thermal Imaging) method, etc.

Meanwhile, each of the first and second hole control layers HCL1 and HCL2 may include a hole block layer corresponding to the hole block area. In this case, each of the first and second hole control layers HCL1 and HCL2 may include a hole block material. In addition, each of the first and second hole control layers HCL1 and HCL2 may further include an electric charge generating material.

The first electron control layer ECL1 is disposed between the first light emitting layer EML1 and the conductive thin film layer 230. The electrons generated by the conductive thin film layer 230 are provided to the first light emitting layer EML1 through the first electron control layer ECL1.

The second electron control layer ECL2 is disposed between the second light emitting layer EML2 and the second electrode 250. When the second electrode 250 is a cathode electrode layer, the electrons injected from the second electrode 250 are provided to the second light emitting layer EML2 through the insulating layer 300 and the second electron control layer ECL2.

Each of the first and second electron control layers ECL1 and ECL2 may correspond to at least one of an electron injection area, an electron transport area, and a hole block area. Each of the first and second electron control layers

ECL1 and ECL2 may have a single-layer structure of a single material or plural different materials or a multi-layer structure of layers formed of different materials.

For instance, each of the first and second electron control layers ECL1 and ECL2 may include at least one of an electron injection layer corresponding to the electron injection layer, an electron transport layer corresponding to the electron transport area, and a single layer having an electron injection function and an electron transport function.

Each of the first and second electron control layers ECL1 and ECL2 may include at least one of an electron transport material and an electron injection material. For instance, the electron transport material may include, but not limited to, Alq3(Tris(8-hydroxyquinolinato)aluminum), TPBi(1,3,5-Tri(1-phenyl-1H-benzo[d]imidazol-2-yl)phenyl), BCP(2,9-Dimethyl-4,7-diphenyl-1,10-phenanthroline), Bphen(4,7-Diphenyl-1,10-phenanthroline), TAZ(3-(4-Biphenyl)-4-phenyl-5-tert-butylphenyl-1,2,4-triazole), NTAZ(4-(Naphthalen-1-yl)-3,5-diphenyl-4H-1,2,4-triazole), tBu-PBD(2-(4-Biphenyl)-5-(4-tert-butylphenyl)-1,3,4-oxadiazole), BAQ(Bis(2-methyl-8-quinolinolato-N1,O8)-(1,1'-Biphenyl-4-olato)aluminum), Beq2(berylliumbis(benzoquinolin-10-olate), ADN(9,10-di(naphthalene-2-yl)anthracene), or a compound thereof.

In addition, the electron injection material may include a lanthanide-based metal, e.g., LiF, LiQ (Lithium quinolate), Li₂O, BaO, NaCl, CsF, Yb, etc., or a metal halide, e.g., RbCl, RbI, etc., but it should not be limited thereto or thereby. The electron transport layer may include a mixture of an electron transport material and an organo metal salt with insulating property.

The organo metal salt has an energy band gap of about 4 eV or more. In detail, the organo metal salt may include, e.g., metal acetate, metal benzoate, metal acetoacetate, metal acetylacetonate, or metal stearate.

Each of the first and second electron control layers ECL1 and ECL2 may be formed by various methods, e.g., a vacuum deposition method, a spin coating method, a cast method, an LB (Langmuir-Blodgett) method, an inkjet printing method, a laser printing method, an LITI (Laser Induced Thermal Imaging) method, etc.

The organic light emitting element 200 according to the present disclosure should not be limited to the above-mentioned structure and function. For instance, the organic light emitting element 200 may include three light emitting units and two conductive thin film layers interposed between the three light emitting units. In this structure, the insulating layer 300 may insulate the two conductive thin film layers from the second electrode 250.

As an example, the insulating layer 300 corresponds to a separate component disposed on the second light emitting unit 250, but the present disclosure should not be limited thereto or thereby. That is, the insulating layer 300 may be provided as a layer that performs a function of the second light emitting unit 250. For instance, the insulating layer 300 may correspond to the electron injection area, and the second electron control layer ECL2 of the second light emitting unit 240 may include the electron transport area and the hole block area. In this structure, the insulating layer 300 may perform a function of the electron injection area of the second light emitting unit 240. Similarly, the insulating layer 300 may be not only the electron injection area but also the electron transport area and the hole block area. In addition, in the case that the organic light emitting element 200 has the inverted structure, the insulating layer 300 may be one of the hole injection area, the hole transport area, and the electron block area.

The insulating layer **300** may include, for example, at least one of LiQ and LiF. As an example, in the non-inverted structure, the insulating layer **300** may include the host material of the first and second hole control layers HCL1 and HCL2 to block the injection/transport of the electrons or a material of the first and second electron control layers ECL1 and ECL2, which has a low electron conductivity. Accordingly, the electrons injected from the first electrode part **251** that is the cathode are blocked, and thus the lateral leakage current may be effectively prevented.

The insulating layer **300** has a thickness of about 1 nm to about 10 nm. When the thickness of the insulating layer **300** is smaller than about 1 nm, the insulating layer **300** may not be sufficiently thick to properly perform an insulating function with respect to the conductive thin film layer **230** in the first area A1 (refer to FIG. 3A). When the thickness of the insulating layer **300** exceeds about 10 nm, the insulating layer **300** may be too thick to perform the function of the electron injection/transport with respect to the second light emitting unit **240** in the second area A2 (refer to FIG. 3A).

As an example, in the inverted structure, the insulating layer **300** may include the host material of the first and second electron control layers ECL1 and ECL2 to block the injection/transport of the holes or a material of the first and second hole control layers HCL1 and HCL2, which has a low hole conductivity. Accordingly, the holes injected from the first electrode part **251** that is the anode are blocked, and thus the lateral leakage current may be effectively prevented.

FIGS. 8A to 8F are cross-sectional views showing stages in a method of manufacturing a display panel according to an exemplary embodiment.

Referring to FIG. 8A, the pixel circuit layer PC is formed on the base substrate BS, and the first insulating layer IL1 is formed on the pixel circuit layer PC. A driving contact hole CNT_{Dr} is formed through the first insulating layer IL1. A portion of the pixel circuit layer PC is exposed through the driving contact hole CNT_{Dr}.

Referring to FIG. 8B, the first electrode **210** and the auxiliary electrode **100** are formed on the first insulating layer IL1. As described above, the first end of the first electrode **210** is disposed in the driving contact hole CNT_{Dr} formed through the first insulating layer IL1 and makes contact with the pixel circuit layer PC. The second end of the first electrode **210** extends from the first end of the first electrode **210** and is disposed in the second area A2. The auxiliary electrode **100** is spaced apart from the first electrode **210** and disposed in the first area A1.

As shown in FIG. 8C, the pixel definition layer PDL is formed on the first electrode **210** and the auxiliary electrode **100**. Then, the first light emitting unit **220**, the conductive thin film layer **230**, and the second light emitting unit **240** are sequentially formed on the pixel definition layer PDL, the first electrode **210**, and the auxiliary electrode **100**.

Referring to FIG. 8D, the first contact hole CNT1 is formed in the first area A1. The first contact hole CNT1 is formed by removing portions (hereinafter, referred to as "removed layers") of the first light emitting unit **220**, the conductive thin film layer **230**, and the second light emitting unit **240** in the first area A1 to expose a portion, e.g., of the upper surface, of the first auxiliary electrode **100**. As an example, since the removed layers are removed, the first, second, and third exposing surfaces **221**, **231**, and **241** are formed, e.g., the first through third exposing surfaces **221** through **241** are lateral surfaces facing the interior of the first contact hole CNT1 and defining a sidewall of the first contact hole CNT1.

Referring to FIG. 8E, the insulating layer **300** is formed, e.g., conformally, on the second light emitting unit **240**. The first part **310** is formed, e.g., conformally, in the first contact hole CNT1 and makes contact with the exposed auxiliary electrode **100**. Then, as shown in FIG. 8F, the first electrode part **251** and the second insulating layer IL2 are formed on the insulating layer **300**.

FIGS. 9A to 9C are cross-sectional views showing stages in a method of manufacturing a display panel according to an exemplary embodiment.

Referring to FIG. 9A, components including the pixel circuit layer PC, the insulating layer **300**, and elements disposed between the pixel circuit layer PC and the insulating layer **300** are sequentially stacked on the base substrate BS. A method of stacking the pixel circuit layer PC, the insulating layer **300**, and elements disposed between the pixel circuit layer PC and the insulating layer **300** are the same as the manufacturing method described with reference to FIGS. 8A to 8E, and thus details thereof will be omitted.

Referring to FIG. 9B, the second contact hole CNT2 is formed through the insulating layer **300**. The second contact hole CNT2 is formed by removing a portion of the first part **310** in the first area A1 to expose a portion of the auxiliary electrode **100**. As an example, the portion of the first part **310** may be removed by using a laser drilling method. When the portion of the first part **310** is removed, the fourth exposing surface **301** is formed.

As shown in FIG. 9C, the second electrode **250** is formed on the insulating layer **300**. The first electrode part **251** makes contact with the auxiliary electrode **100** exposed through the second contact hole CNT2. The second insulating layer IL2 is formed on the second electrode **250**.

By way of summation and review, the present disclosure provides a display panel capable of preventing poor emission of an organic light emitting element due to a lateral leakage current. The present disclosure also provides a method of manufacturing the display panel, as well as a display device having the display panel.

That is, according to embodiments, an insulating layer is disposed between the conductive thin film layer and the second electrode to insulate the conductive thin film layer from the second electrode. Accordingly, the lateral leakage current may be prevented from flowing through the conductive thin film layer, and defect in light emission of the organic light emitting element may be prevented from occurring due to the lateral leakage current.

Example embodiments have been disclosed herein, and although specific terms are employed, they are used and are to be interpreted in a generic and descriptive sense only and not for purpose of limitation. In some instances, as would be apparent to one of ordinary skill in the art as of the filing of the present application, features, characteristics, and/or elements described in connection with a particular embodiment may be used singly or in combination with features, characteristics, and/or elements described in connection with other embodiments unless otherwise specifically indicated. Accordingly, it will be understood by those of skill in the art that various changes in form and details may be made without departing from the spirit and scope of the present invention as set forth in the following claims.

What is claimed is:

1. A method of manufacturing a display panel, the method comprising:
 - forming an auxiliary electrode in a first area defined in a base substrate;

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forming a first electrode in a second area defined in the
 base substrate and spaced apart from the first area when
 viewed in a plan view;
 forming a first light emitting unit on the first electrode;
 forming an conductive thin film layer on the first light 5
 emitting unit;
 forming a second light emitting unit on the conductive
 thin film layer;
 removing at least a portion of the first light emitting unit,
 the conductive thin film layer, and the second light 10
 emitting unit to form a first contact hole through which
 an upper surface of the auxiliary electrode is exposed;
 forming a insulating layer on an exposing surface of the
 conductive thin film layer, which is exposed through
 the first contact hole; and 15
 forming a second electrode on the insulating layer.

2. The method as claimed in claim 1, further comprising
 removing a portion of the insulating layer to form a second
 contact hole, through which at least a portion of the upper
 surface of the auxiliary electrode is exposed, through the 20
 insulating layer.

3. The method as claimed in claim 2, wherein forming the
 second contact hole is performed after forming the insulat-
 ing layer and before forming the second electrode.

4. The method as claimed in claim 1, wherein the first 25
 light emitting unit, the conductive thin film layer, and the
 second light emitting unit are removed using a laser drilling
 method.

* * * * *

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专利名称(译)	能够防止有机发光元件的发光不良的显示面板的制造方法		
公开(公告)号	US10439161	公开(公告)日	2019-10-08
申请号	US16/020572	申请日	2018-06-27
[标]申请(专利权)人(译)	三星显示有限公司		
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IPC分类号	H01L51/50 H01L51/52 H01L51/00 H01L51/56 H01L27/32		
CPC分类号	H01L51/5228 H01L27/3246 H01L51/5044 H01L27/3209 H01L51/56 H01L51/0096 H01L51/5206 H01L2251/301 H01L2251/558 H01L2251/5392		
优先权	1020160090947 2016-07-18 KR		
其他公开文献	US20180309085A1		
外部链接	Espacenet		

摘要(译)

显示面板包括：在基板上的辅助电极，与辅助电极隔开的第一电极，在辅助电极和第一电极上的第一发光单元，在第一发光单元上的导电薄膜层，第二光。在导电薄膜层上的发光单元，穿过导电薄膜层以暴露辅助电极的第一接触孔，在第一接触孔中的绝缘层以及包括第一电极部分和第二电极部分的第二电极，第一电极部分在第一接触孔中的绝缘层上，第二电极部分与第一电极重叠并且在第二发光单元上，其中绝缘层在第一电极部分和导电薄膜层之间。

